FUJITSU MICROELECTRONICS
DATA SHEET

DS07–12624–3E

8-bit Microcontrollers

CMOS

F²MC-8FX MB95160MA Series

MB95168MA/F168MA/F168NA/F168JA/ MB95FV100D-103

■ DESCRIPTION

The MB95160MA series is general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers contain a variety of peripheral functions.

Note : F²MC is the abbreviation of FUJITSU Flexible Microcontroller.

■ FEATURE

- F²MC-8FX CPU core
  Instruction set optimized for controllers
  - Multiplication and division instructions
  - 16-bit arithmetic operations
  - Bit test branch instruction
  - Bit manipulation instructions etc.
- Clock
  - Main clock
  - Main PLL clock
  - Sub clock
  - Sub PLL clock

(Continued)

For the information for microcontroller supports, see the following web site.
This web site includes the **"Customer Design Review Supplement"** which provides the latest cautions on system development and the minimal requirements to be checked to prevent problems before the system development.

http://edevice.fujitsu.com/micom/en-support/

Copyright©2008-2009 FUJITSU MICROELECTRONICS LIMITED All rights reserved
2009.3

(Continued)

- Timer
  - 8/16-bit compound timer × 2 channels
    Can be used to interval timer, PWC timer, PWM timer and input capture.
  - 8/16-bit PPG × 2 channels
  - 16-bit PPG × 1 channel
  - Time-base timer × 1 channel
  - Watch prescaler × 1 channel
- LIN-UART × 1 channel
  - LIN function, clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable
  - Full duplex double buffer
- UART/SIO × 1 channel
  - Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable
  - Full duplex double buffer
- I^2C × 1 channel
  Built-in wake-up function
- External interrupt × 8 channels
  - Interrupt by edge detection (rising, falling, or both edges can be selected)
  - Can be used to recover from low-power consumption (standby) modes.
- 8/10-bit A/D converter × 8 channels
  8-bit or 10-bit resolution can be selected.
- LCD controller (LCDC)
  - 32 SEG × 4 COM (Max 128 pixels)
  - With blinking function
- Low-power consumption (standby) mode
  - Stop mode
  - Sleep mode
  - Watch mode
  - Time-base timer mode
- I/O port
  - The number of maximum ports : Max 52
  - Port configuration
    - General-purpose I/O ports (N-ch open drain) : 2 ports
    - General-purpose I/O ports (CMOS) : 50 ports
- Programmable input voltage levels of port
  Automotive input level / CMOS input level / hysteresis input level
- Flash memory security function (Flash memory product only)
  Protects the content of Flash memory

■ PRODUCT LINEUP

Parameter \ Part number		MB95168MA	MB95F168MA	MB95F168NA	MB95F168JA
Type		Mask ROM product	Flash memory product		
ROM capacity		60 Kbytes			
RAM capacity		2 Kbytes			
Reset output		Yes/No selectable	Yes		No
Option*	Clock system	Dual clock			
	Low voltage detection reset	Yes/No selectable	No	Yes	
	Clock supervisor	Yes/No selectable	No		Yes
CPU functions		Number of basic instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 bytes Data bit length : 1, 8, and 16 bits Minimum instruction execution time : 61.5 ns (at machine clock frequency 16.25 MHz) Interrupt processing time : 0.6 µs (at machine clock frequency 16.25 MHz)			
Peripheral functions	Ports (Max 52 ports)	General-purpose I/O port (N-ch open drain) : 2 ports General-purpose I/O port (CMOS) : 50 ports Programmable input voltage levels of port : Automotive input level / CMOS input level / hysteresis input level			
	Time-base timer (1 channel)	Interrupt cycle : 0.5 ms, 2.1 ms, 8.2 ms, 32.8 ms (at main oscillation clock 4 MHz)			
	Watchdog timer	Reset generated cycle At main oscillation clock 10 MHz : Min 105 ms At sub oscillation clock 32.768 kHz (for dual clock product) : Min 250 ms			
	Wild register	Capable of replacing 3 bytes of ROM data			
	I^2C (1 channel)	Master/slave sending and receiving Bus error function and arbitration function Detecting transmitting direction function Start condition repeated generation and detection functions Built-in wake-up function			
	UART/SIO (1 channel)	Data transfer capable in UART/SIO Full duplex double buffer, variable data length (5/6/7/8-bit), built-in baud rate generator NRZ type transfer format, error detected function LSB-first or MSB-first can be selected. Clock synchronous (SIO) or clock asynchronous (UART) serial data transfer capable			
	LIN-UART (1 channel)	Dedicated reload timer allowing a wide range of communication speeds to be set. Full duplex double buffer. Capable of serial data transfer synchronous or asynchronous to clock signal. LIN functions available as the LIN master or LIN slave.			
	8/10-bit A/D converter (8 channels)	8-bit or 10-bit resolution can be selected.			

(Continued)

(Continued)

Parameter \ Part number		MB95168MA	MB95F168MA	MB95F168NA	MB95F168JA
Peripheral functions	LCD controller (LCDC)	COM output : 4 (Max) SEG output : 32 (Max) LCD drive power supply (bias) pin : 4 32 SEG × 4 COM : 128 pixels can be displayed. Duty LCD mode Operable in LCD standby mode With blinking function Built-in division resistance for LCD drive			
	8/16-bit compound timer (2 channels)	Each channel of the timer can be used as “8-bit timer × 2 channels” or “16-bit timer × 1 channel”. Built-in timer function, PWC function, PWM function, capture function, and square wave form output Count clock : 7 internal clocks and external clock can be selected.			
	16-bit PPG (1 channel)	PWM mode or one-shot mode can be selected. Counter operating clock : Eight selectable clock sources Support for external trigger start			
	8/16-bit PPG (2 channels)	Each channel of the PPG can be used as “8-bit PPG × 2 channels” or “16-bit PPG × 1 channel”. Counter operating clock : Eight selectable clock sources			
	Watch counter	Count clock : Four selectable clock sources (125 ms, 250 ms, 500 ms, or 1 s) Counter value can be set from 0 to 63. (Capable of counting for 1 minute when selecting clock source 1 second and setting counter value to 60)			
	Watch prescaler (1 channel)	4 selectable interval times (125 ms, 250 ms, 500 ms, or 1 s)			
	External interrupt (8 channels)	Interrupt by edge detection (rising, falling, or both edges can be selected.) Can be used to recover from standby modes.			
Flash memory		—	Supports automatic programming, Embedded Algorithm Write/Erase/Erase-Suspend/Resume commands A flag indicating completion of the algorithm Number of write/erase cycles (Minimum) : 10000 times Data retention time: 20 years Erase can be performed on each block Block protection with external programming voltage Flash Security Feature for protecting the content of the Flash		
Standby mode		Sleep, stop, watch, and time-base timer			

* : For details of option, refer to “■ MASK OPTION”.

Note : Part number of evaluation product in MB95160MA series is MB95FV100D-103. When using it, the MCU board (MB2146-303A-E) is required.

■ OSCILLATION STABILIZATION WAIT TIME

The initial value of the main clock oscillation stabilization wait time is fixed to the maximum value. The maximum value is shown as follows.

Oscillation stabilization wait time	Remarks
$(2^{14}-2)/F_{CH}$	Approx. 4.10 ms (at main oscillation clock 4 MHz)

■ PACKAGES AND CORRESPONDING PRODUCTS

Package \ Part number	MB95168MA	MB95F168MA/ F168NA/F168JA	MB95FV100D-103
FPT-64P-M23	○	○	×
FPT-64P-M24	○	○	×
BGA-224P-M08	×	×	○

○ : Available
× : Unavailable

■ DIFFERENCES AMONG PRODUCTS AND NOTES ON SELECTING PRODUCTS

• Notes on Using Evaluation Products

The evaluation product has not only the functions of the MB95160MA series but also those of other products to support software development for multiple series and models of the F^{2}MC-8FX family. The I/O addresses for peripheral resources not used by the MB95160MA series are therefore access-barred. Read/write access to these access-barred addresses may cause peripheral resources supposed to be unused to operate, resulting in unexpected malfunctions of hardware or software.

Particularly, do not use word access to odd numbered byte address in the prohibited areas (If these access are used, the address may be read or written unexpectedly).

Also, as the read values of prohibited addresses on the evaluation product are different to the values on the Flash memory products or Mask ROM products, do not use these values in the program.

The functions corresponding to certain bits in single-byte registers may not be supported depending on the type of Flash memory products and Mask ROM products. However, reading or writing to these bits will not cause malfunction of the hardware. Also, the products with either evaluation, Flash memory or Mask ROM are designed to have the same operation in software and hardware.

• Difference of Memory Spaces

If the amount of memory on the evaluation product is different from that of the Flash memory and Mask ROM products, carefully check the difference in the amount of memory from the model to be actually used when developing software.

For details of memory space, refer to “■ CPU CORE”.

• Current Consumption

Current in Flash memory products is consumed more than Mask ROM products.
For details of current consumption, refer to “■ ELECTRICAL CHARACTERISTICS”.

• Package

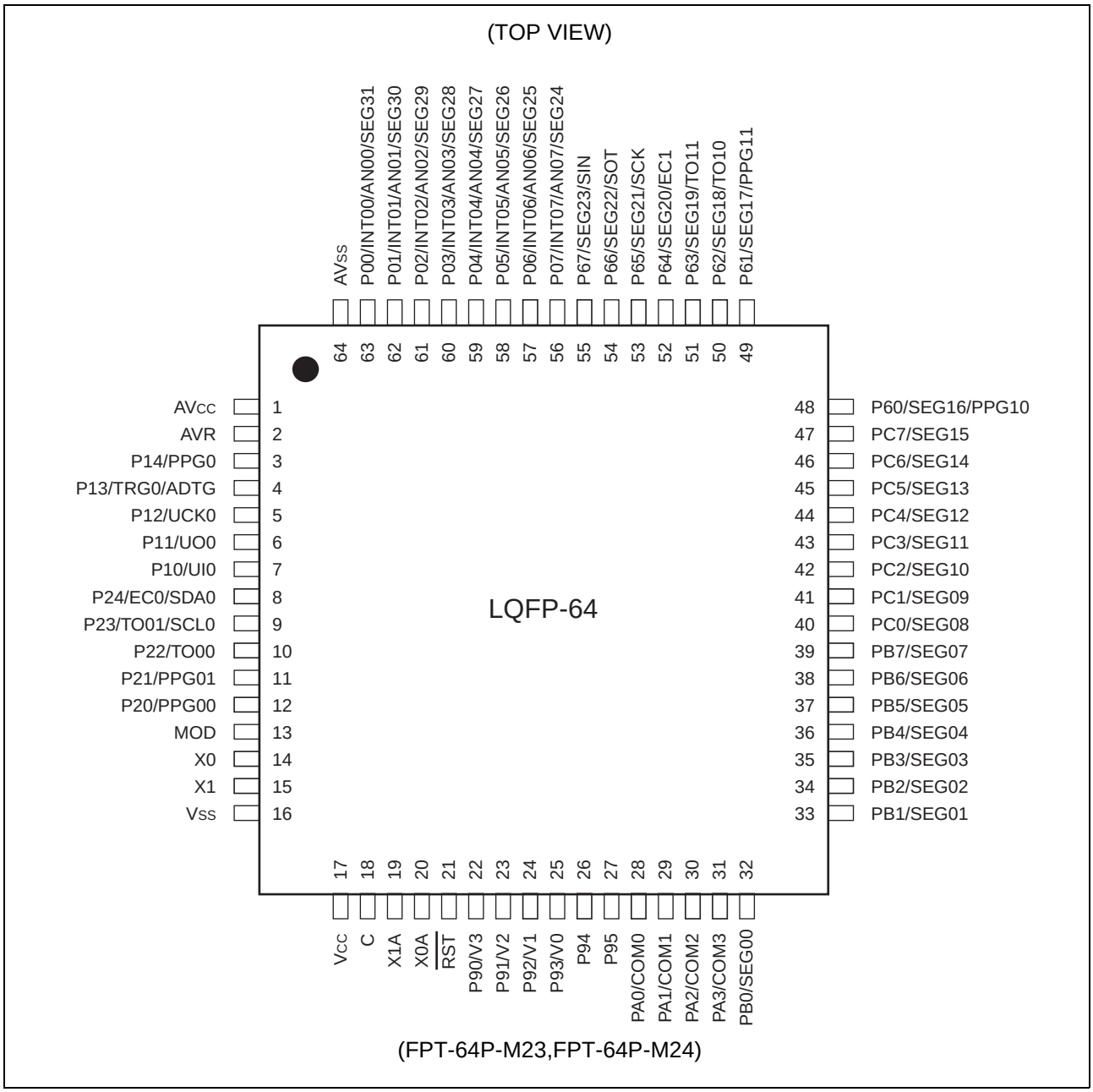
For details of information on each package, refer to “■ PACKAGES AND CORRESPONDING PRODUCTS” and “■ PACKAGE DIMENSIONS”.

• Operating voltage

The operating voltage is different among the evaluation, Flash memory products and Mask ROM products.

For details of operating voltage, refer to “■ ELECTRICAL CHARACTERISTICS”

■ PIN ASSIGNMENT



■ PIN DESCRIPTION

Pin no.	Pin name	I/O circuit type*1	Function
1	AV_{CC}	—	A/D converter power supply pin
2	AVR	—	A/D converter reference input pin
3	P14/PPG0	H	General-purpose I/O port. The pin is shared with 16-bit PPG ch.0 output.
4	P13/TRG0/ ADTG		General-purpose I/O port. The pin is shared with 16-bit PPG ch.0 trigger input (TRG0) and A/D converter trigger input (ADTG) .
5	P12/UCK0		General-purpose I/O port. The pin is shared with UART/SIO ch.0 clock I/O.
6	P11/UO0		General-purpose I/O port. The pin is shared with UART/SIO ch.0 data output.
7	P10/UI0	G	General-purpose I/O port. The pin is shared with UART/SIO ch.0 data input.
8	P24/EC0/ SDA0	I	General-purpose I/O port. The pin is shared with 8/16-bit compound timer ch.0 clock input (EC0) and I^2C ch.0 data I/O (SDA0) .
9	P23/TO01/ SCL0		General-purpose I/O port. The pin is shared with 8/16-bit compound timer ch.0 output (TO01) and I^2C ch.0 clock I/O (SCL0) .
10	P22/TO00	H	General-purpose I/O port. The pin is shared with 8/16-bit compound timer ch.0 output.
11	P21/PPG01		General-purpose I/O port. The pin is shared with 8/16-bit PPG ch.0 output.
12	P20/PPG00		General-purpose I/O port. The pin is shared with 8/16-bit PPG ch.0 output.
13	MOD	B	Operating mode designation pin
14	X0	A	Main clock oscillation pins
15	X1		
16	V_{SS}	—	Power supply pin (GND)
17	V_{CC}	—	Power supply pin
18	C	—	Capacitor connection pin
19	X1A	A	Sub clock oscillation pins (32 kHz)
20	X0A		
21	$\overline{RST}$	B’	Reset pin
22	P90/V3	R	General-purpose I/O ports. The pins are shared with power supply pin for LCDC drive.
23	P91/V2		
24	P92/V1		
25	P93/V0		

(Continued)

Pin no.	Pin name	I/O circuit type*1	Function
26	P94	S	General-purpose I/O ports.
27	P95*2		
28	PA0/COM0	M	General-purpose I/O ports. The pins are shared with LCDC COM output (COM0 to COM3).
29	PA1/COM1		
30	PA2/COM2		
31	PA3/COM3		
32	PB0/SEG00	M	General-purpose I/O ports. The pins are shared with LCDC SEG output (SEG00 to SEG07).
33	PB1/SEG01		
34	PB2/SEG02		
35	PB3/SEG03		
36	PB4/SEG04		
37	PB5/SEG05		
38	PB6/SEG06		
39	PB7/SEG07		
40	PC0/SEG08	M	General-purpose I/O ports. The pins are shared with LCDC SEG output (SEG08 to SEG15).
41	PC1/SEG09		
42	PC2/SEG10		
43	PC3/SEG11		
44	PC4/SEG12		
45	PC5/SEG13		
46	PC6/SEG14		
47	PC7/SEG15		
48	P60/SEG16/ PPG10	M	General-purpose I/O ports. The pins are shared with LCDC SEG output (SEG16, SEG17) and 8/16-bit PPG ch.1 output (PPG10, PPG11) .
49	P61/SEG17/ PPG11		
50	P62/SEG18/ TO10		General-purpose I/O port. The pin is shared with LCDC SEG output (SEG18) and 8/16-bit compound timer ch.1 output (TO10) .
51	P63/SEG19/ TO11		General-purpose I/O port. The pin is shared with LCDC SEG output (SEG19) and 8/16-bit compound timer ch.1 output (TO11) .
52	P64/SEG20/ EC1		General-purpose I/O port. The pin is shared with LCDC SEG output (SEG20) and 8/16-bit compound timer ch.1 clock input (EC1) .
53	P65/SEG21/ SCK		General-purpose I/O port. The pin is shared with LCDC SEG output (SEG21) and LIN-UART clock I/O (SCK) .
54	P66/SEG22/ SOT		General-purpose I/O port. The pin is shared with LCDC SEG output (SEG22) and LIN-UART data output (SOT) .

(Continued)

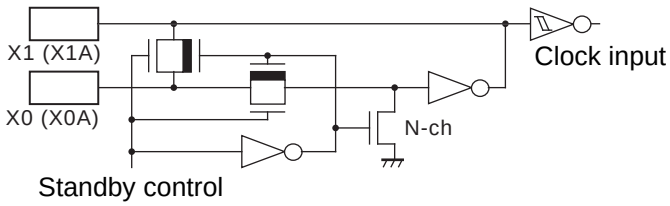
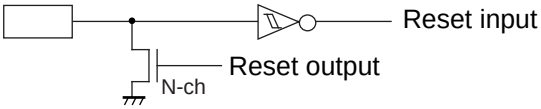
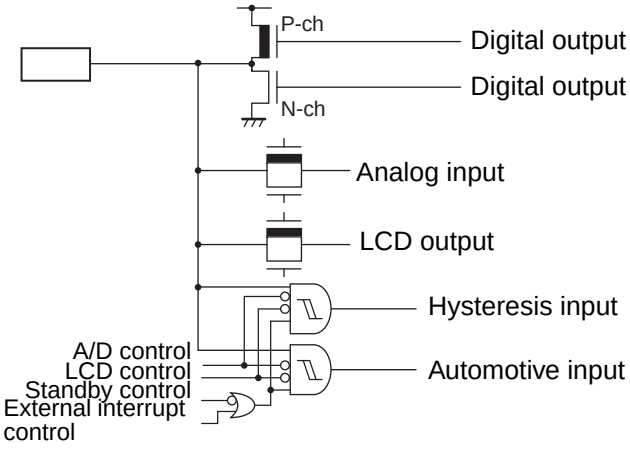
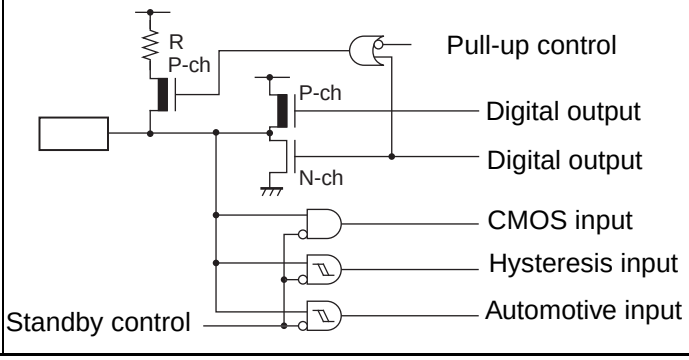
(Continued)

Pin no.	Pin name	I/O circuit type*1	Function
55	P67/SEG23/ SIN	N	General-purpose I/O port. The pin is shared with LCDC SEG output (SEG23) and LIN-UART data input (SIN) .
56	P07/INT07/ AN07/SEG24	F	General-purpose I/O ports. The pins are shared with external interrupt input (INT00 to INT07), A/D analog input (AN00 to AN07) and LCDC SEG output (SEG31 to SEG24) .
57	P06/INT06/ AN06/SEG25		
58	P05/INT05/ AN05/SEG26		
59	P04/INT04/ AN04/SEG27		
60	P03/INT03/ AN03/SEG28		
61	P02/INT02/ AN02/SEG29		
62	P01/INT01/ AN01/SEG30		
63	P00/INT00/ AN00/SEG31		
64	AV_{SS}	—	Power supply pin (GND) of A/D converter

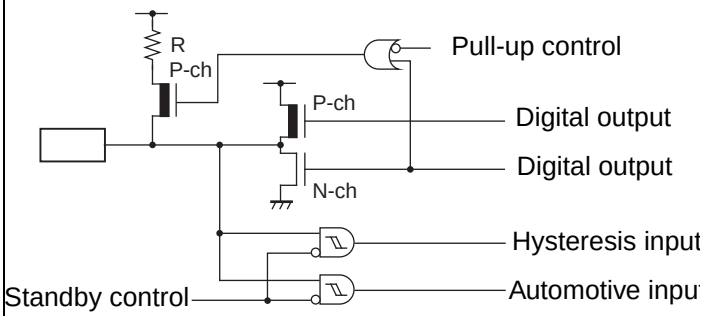
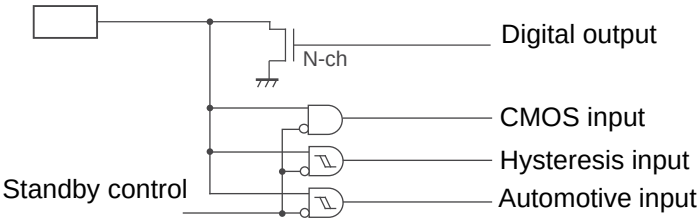
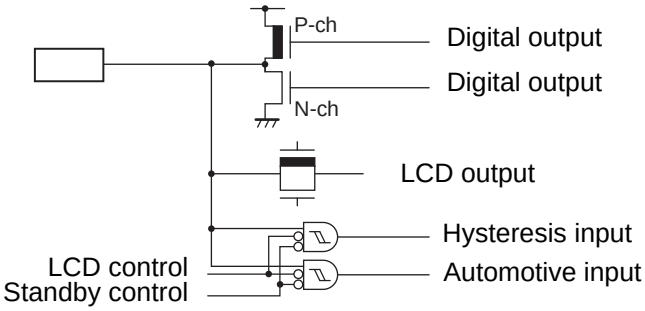
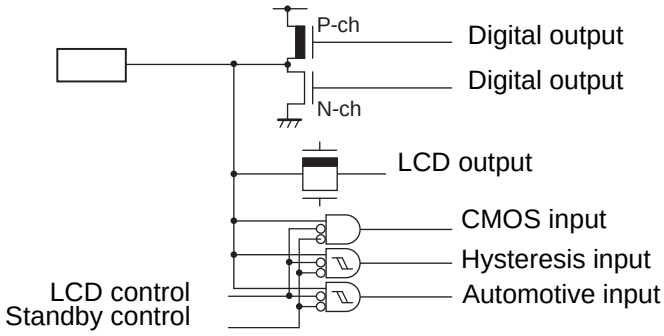
*1 : Refer to “■ I/O CIRCUIT TYPE” for details on the I/O circuit types.

*2 : When using P07 for segment output (SEG24) of LCDC, P95 can not be used as an output port. It can be used only as an input port.

■ I/O CIRCUIT TYPE

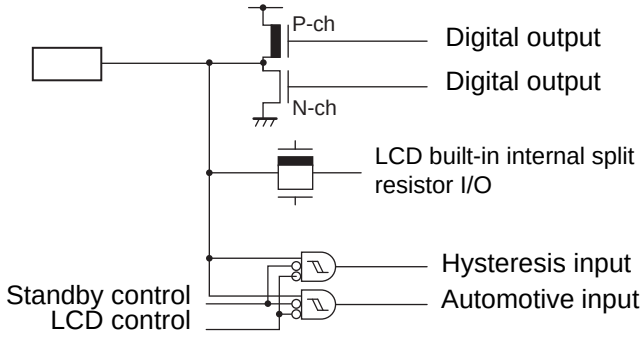
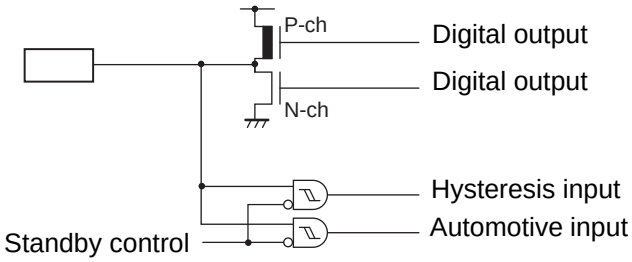
Type	Circuit	Remarks
A		• Oscillation circuit • High-speed side Feedback resistance : approx. 1 MΩ • Low-speed side Feedback resistance : approx. 10 MΩ
B		• Only for input • Hysteresis input
B’		• Hysteresis input • Reset output
F		• CMOS output • LCD output • Hysteresis input • Analog input • Automotive input
G		• CMOS output • CMOS input • Hysteresis input • With pull-up control • Automotive input

(Continued)

Type	Circuit	Remarks
H		• CMOS output • Hysteresis input • With pull-up control • Automotive input
I		• N-ch open drain output • CMOS input • Hysteresis input • Automotive input
M		• CMOS output • LCD output • Hysteresis input • Automotive input
N		• CMOS output • LCD output • CMOS input • Hysteresis input • Automotive input

(Continued)

(Continued)

Type	Circuit	Remarks
R		• CMOS output • LCD power supply • Hysteresis input • Automotive input
S		• CMOS output • LCD power supply • Hysteresis input • Automotive input

■ HANDLING DEVICES

• Preventing Latch-up

Care must be taken to ensure that maximum voltage ratings are not exceeded when they are used.

Latch-up may occur on CMOS ICs if voltage higher than V_{CC} or lower than V_{SS} is applied to input and output pins
other than medium- and high-withstand voltage pins or if higher than the rating voltage is applied between V_{CC} pin and V_{SS} pin.

When latch-up occurs, power supply current increases rapidly and might thermally damage elements.

• Stable Supply Voltage

Supply voltage should be stabilized.

A sudden change in power-supply voltage may cause a malfunction even within the guaranteed operating range of the Vcc power-supply voltage.

For stabilization, in principle, keep the variation in Vcc ripple (p-p value) in a commercial frequency range (50/60 Hz) not to exceed 10% of the standard Vcc value and suppress the voltage variation so that the transient variation rate does not exceed 0.1 V/ms during a momentary change such as when the power supply is switched.

• Precautions for Use of External Clock

Even when an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from sub clock mode or stop mode.

• Serial communication

There is a possibility to receive wrong data due to noise or other causes on the serial communication.

Therefore, design a printed circuit board so as to avoid noise.

Consider receiving of wrong data when designing the system. For example apply a checksum and retransmit the data if an error occurs.

PIN CONNECTION

• Treatment of Unused Pin

Leaving unused input pins unconnected can cause abnormal operation or latch-up, leaving to permanent damage. Unused input pins should always be pulled up or down through resistance of at least 2 kΩ. Any unused input/output pins may be set to output mode and left open, or set to input mode and treated the same as unused input pins. If there is unused output pin, make it to open.

• Power Supply Pins

In products with multiple V_{CC} or V_{SS} pins, the pins of the same potential are internally connected in the device to avoid abnormal operations including latch-up. However, you must connect the pins to external power supply and a ground line to lower the electro-magnetic emission level, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating.

Moreover, connect the current supply source with the V_{CC} and V_{SS} pins of this device at the low impedance.

It is also advisable to connect a ceramic bypass capacitor of approximately 0.1 µF between V_{CC} and V_{SS} pins near this device.

- Mode Pin (MOD)

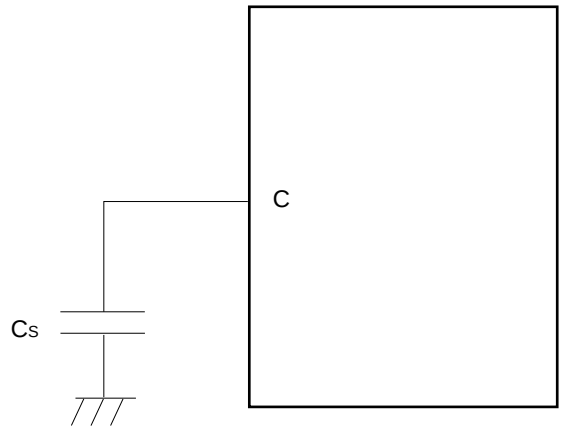
  Connect the MOD pin directly to V_{CC} or V_{SS}.

  To prevent the device unintentionally entering test mode due to noise, lay out the printed circuit board so as to minimize the distance from the MOD pin to V_{CC} or V_{SS} and to provide a low-impedance connection.

- C Pin

  Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. A bypass capacitor of V_{CC} pin must have a capacitance value higher than C_S. For connection of smoothing capacitor C_S, refer to the diagram below.

  • C pin connection diagram



- Analog Power Supply

  Always set the same potential to AV_{CC} and V_{CC} pins. When $V_{CC} > AV_{CC}$, the current may flow through the AN00 to AN07 pins.

- Treatment of Power Supply Pins on A/D Converter

  Connect to be $AV_{CC} = V_{CC}$ and $AV_{SS} = AVR = V_{SS}$ even if the A/D converter is not in use.

  Noise riding on the AV_{CC} pin may cause accuracy degradation. So, connect approx. 0.1 µF ceramic capacitor as a bypass capacitor between AV_{CC} and AV_{SS} pins in the vicinity of this device.

■ PROGRAMMING FLASH MEMORY MICROCONTROLLERS USING PARALLEL PROGRAMMER

• Supported Parallel Programmers and Adapters

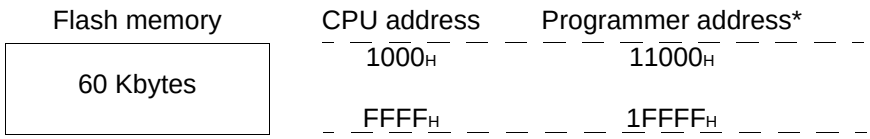
The following table lists supported parallel programmers and adapters.

Package	Applicable adapter model	Parallel programmers
FPT-64P-M23	TEF110-95F168HPMC	AF9708 (Ver 02.35G or more) AF9709/B (Ver 02.35G or more) AF9723+AF9834 (Ver 02.08E or more)
FPT-64P-M24	TEF110-95F168HPMC1	

Note : For information on applicable adapter models and parallel programmers, contact the following:
Flash Support Group, Inc. TEL: +81-53-428-8380

• Sector Configuration

The individual sectors of Flash memory correspond to addresses used for CPU access and programming by the parallel programmer as follows:

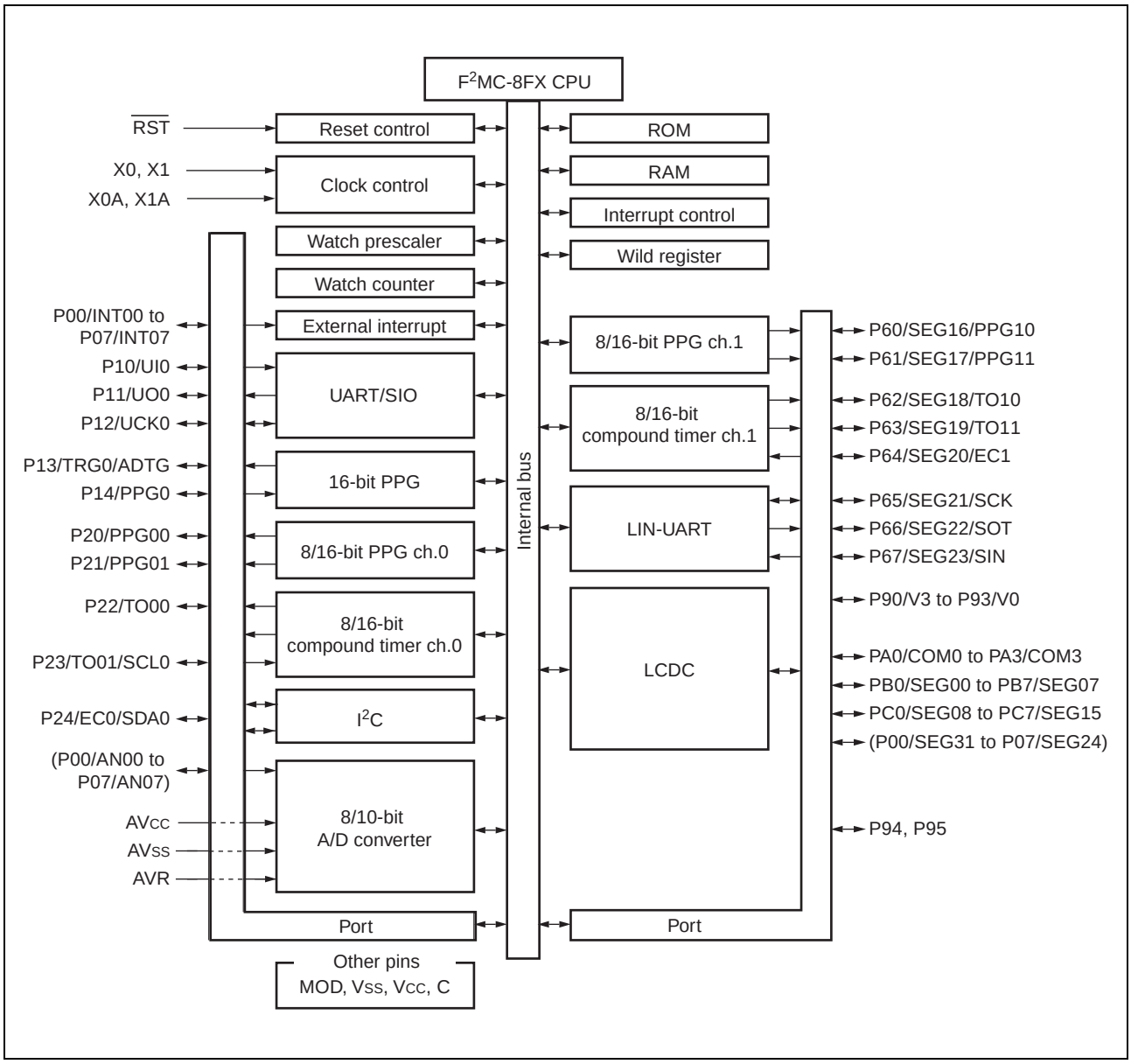


*: Programmer addresses are corresponding to CPU addresses, used when the parallel programmer programs data into Flash memory.
These programmer addresses are used for the parallel programmer to program or erase data in Flash memory.

• Programming Method

1) Set the type code of the parallel programmer to 17222.
2) Load program data to programmer addresses 11000_H to $1FFFF_H$.
3) Programmed by parallel programmer

■ BLOCK DIAGRAM

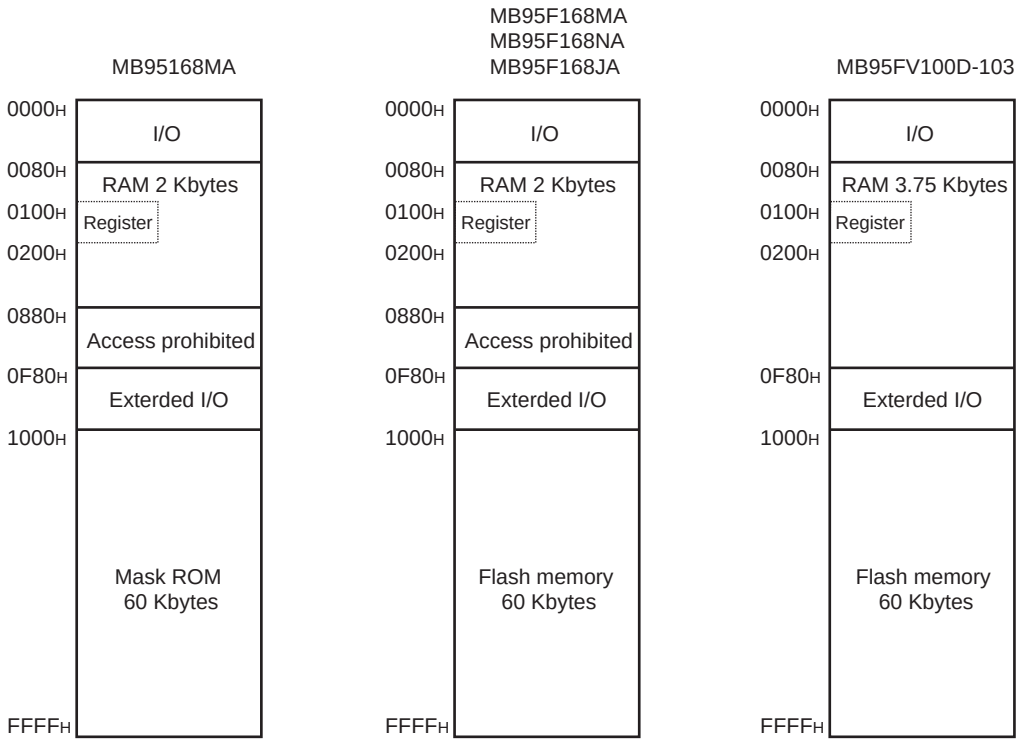


■ CPU CORE

1. Memory space

Memory space of the MB95160MA series is 64 Kbytes and consists of I/O area, data area, and program area. The memory space includes special-purpose areas such as the general-purpose registers and vector table. Memory map of the MB95160MA series is shown below.

- Memory Map



2. Register

The MB95160MA series has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The dedicated registers are as follows:

Program counter (PC) : A 16-bit register to indicate locations where instructions are stored.

Accumulator (A) : A 16-bit register for temporary storage of arithmetic operations. In the case of an 8-bit data processing instruction, the lower 1 byte is used.

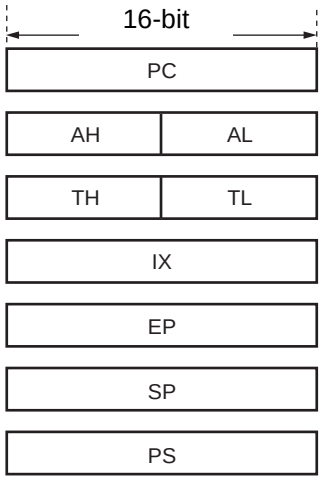
Temporary accumulator (T) : A 16-bit register which performs arithmetic operations with the accumulator. In the case of an 8-bit data processing instruction, the lower 1 byte is used.

Index register (IX) : A 16-bit register for index modification.

Extra pointer (EP) : A 16-bit pointer to point to a memory address.

Stack pointer (SP) : A 16-bit register to indicate a stack area.

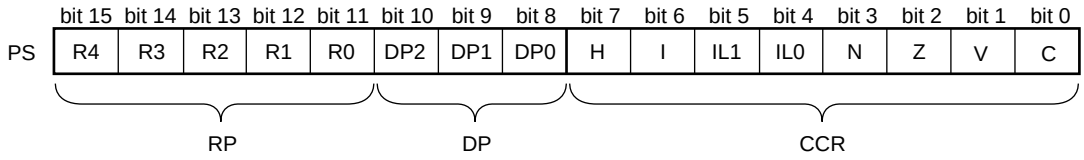
Program status (PS) : A 16-bit register for storing a register bank pointer, a direct bank pointer, and a condition code register.



	Initial Value
: Program counter	$FFFD_H$
: Accumulator	0000_H
: Temporary accumulator	0000_H
: Index register	0000_H
: Extra pointer	0000_H
: Stack pointer	0000_H
: Program status	0030_H

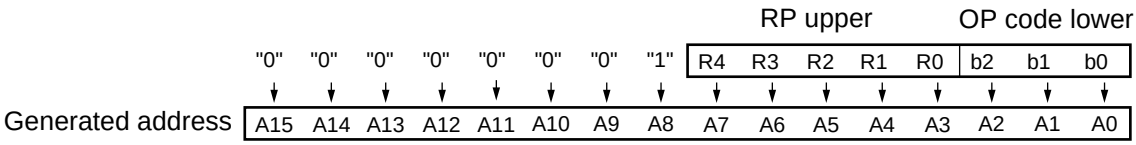
The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and a direct bank pointer (DP) and the lower 8 bits for use as a condition code register (CCR). (Refer to the diagram below.)

• Structure of the Program Status



The RP indicates the address of the register bank currently being used. The relationship between the content of RP and the real address conforms to the conversion rule illustrated below:

- Rule for Conversion of Actual Addresses in the General-purpose Register Area



The DP specifies the area for mapping instructions (16 different instructions such as MOV A, dir) using direct addresses to 0080_H to $00FF_H$.

Direct bank pointer (DP2 to DP0)	Specified address area	Mapping area
XXX_B (no effect to mapping)	0000_H to $007F_H$	0000_H to $007F_H$ (without mapping)
000_B (initial value)	0080_H to $00FF_H$	0080_H to $00FF_H$ (without mapping)
001_B		0100_H to $017F_H$
010_B		0180_H to $01FF_H$
011_B		0200_H to $027F_H$
100_B		0280_H to $02FF_H$
101_B		0300_H to $037F_H$
110_B		0380_H to $03FF_H$
111_B		0400_H to $047F_H$

The CCR consists of the bits indicating arithmetic operation results or transfer data contents and the bits that control CPU operations at interrupt.

H flag : Set to “1” when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Cleared to “0” otherwise. This flag is for decimal adjustment instructions.

I flag : Interrupt is enabled when this flag is set to “1”. Interrupt is disabled when this flag is set to “0”. The flag is set to “0” when reset.

IL1, IL0 : Indicates the level of the interrupt currently enabled. Processes an interrupt only if its request level is higher than the value indicated by these bits.

IL1	IL0	Interrupt level	Priority
0	0	0	High
0	1	1	↕
1	0	2	
1	1	3	Low (no interruption)

N flag : Set to “1” if the MSB is set to “1” as the result of an arithmetic operation. Cleared to “0” when the bit is set to “0”.

Z flag : Set to “1” when an arithmetic operation results in “0”. Cleared to “0” otherwise.

V flag : Set to “1” if the complement on 2 overflows as a result of an arithmetic operation. Cleared to “0” otherwise.

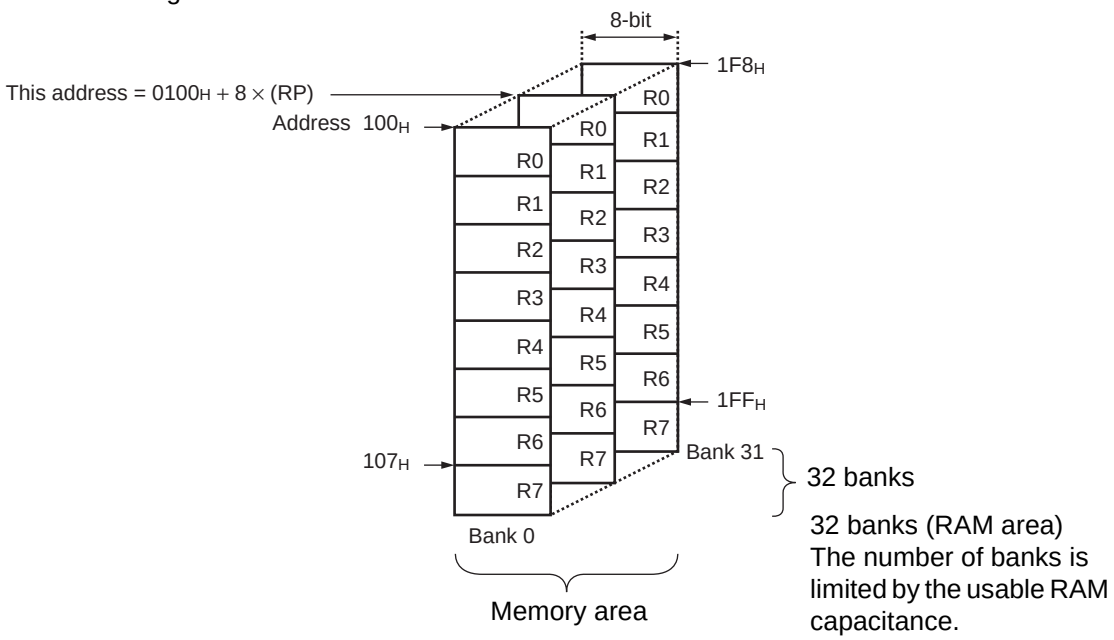
C flag : Set to “1” when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared to “0” otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: 8-bit data storage registers

The general-purpose registers are 8 bits and located in the register banks on the memory. 1-bank contains 8-register. Up to a total of 32 banks can be used on the MB95160MA series. The bank currently in use is specified by the register bank pointer (RP), and the lower 3 bits of OP code indicates the general-purpose register 0 (R0) to general-purpose register 7 (R7).

- Register Bank Configuration



■ I/O MAP

Address	Register abbreviation	Register name	R/W	Initial value
0000H	PDR0	Port 0 data register	R/W	00000000B
0001H	DDR0	Port 0 direction register	R/W	00000000B
0002H	PDR1	Port 1 data register	R/W	00000000B
0003H	DDR1	Port 1 direction register	R/W	00000000B
0004H	—	(Disabled)	—	—
0005H	WATR	Oscillation stabilization wait time setting register	R/W	11111111B
0006H	PLLC	PLL control register	R/W	00000000B
0007H	SYCC	System clock control register	R/W	1010X011B
0008H	STBC	Standby control register	R/W	00000000B
0009H	RSRR	Reset factor register	R/W	XXXXXXXXB
000AH	TBTC	Time-base timer control register	R/W	00000000B
000BH	WPCR	Watch prescaler control register	R/W	00000000B
000CH	WDTC	Watchdog timer control register	R/W	00000000B
000DH	—	(Disabled)	—	—
000EH	PDR2	Port 2 data register	R/W	00000000B
000FH	DDR2	Port 2 direction register	R/W	00000000B
0010H to 0015H	—	(Disabled)	—	—
0016H	PDR6	Port 6 data register	R/W	00000000B
0017H	DDR6	Port 6 direction register	R/W	00000000B
0018H to 001BH	—	(Disabled)	—	—
001CH	PDR9	Port 9 data register	R/W	00000000B
001DH	DDR9	Port 9 direction register	R/W	00000000B
001EH	PDRA	Port A data register	R/W	00000000B
001FH	DDRA	Port A direction register	R/W	00000000B
0020H	PDRB	Port B data register	R/W	00000000B
0021H	DDRB	Port B direction register	R/W	00000000B
0022H	PDRC	Port C data register	R/W	00000000B
0023H	DDRC	Port C direction register	R/W	00000000B
0024H to 002CH	—	(Disabled)	—	—

(Continued)

Address	Register abbreviation	Register name	R/W	Initial value
002D$_H$	PUL1	Port 1 pull-up register	R/W	00000000$_B$
002E$_H$	PUL2	Port 2 pull-up register	R/W	00000000$_B$
002F$_H$ to 0035$_H$	—	(Disabled)	—	—
0036$_H$	T01CR1	8/16-bit compound timer 01 control status register 1 ch.0	R/W	00000000$_B$
0037$_H$	T00CR1	8/16-bit compound timer 00 control status register 1 ch.0	R/W	00000000$_B$
0038$_H$	T11CR1	8/16-bit compound timer 11 control status register 1 ch.1	R/W	00000000$_B$
0039$_H$	T10CR1	8/16-bit compound timer 10 control status register 1 ch.1	R/W	00000000$_B$
003A$_H$	PC01	8/16-bit PPG1 control register ch.0	R/W	00000000$_B$
003B$_H$	PC00	8/16-bit PPG0 control register ch.0	R/W	00000000$_B$
003C$_H$	PC11	8/16-bit PPG1 control register ch.1	R/W	00000000$_B$
003D$_H$	PC10	8/16-bit PPG0 control register ch.1	R/W	00000000$_B$
003E$_H$ to 0041$_H$	—	(Disabled)	—	—
0042$_H$	PCNTH0	16-bit PPG status control register (upper byte) ch.0	R/W	00000000$_B$
0043$_H$	PCNTL0	16-bit PPG status control register (lower byte) ch.0	R/W	00000000$_B$
0044$_H$ to 0047$_H$	—	(Disabled)	—	—
0048$_H$	EIC00	External interrupt circuit control register ch.0/ch.1	R/W	00000000$_B$
0049$_H$	EIC10	External interrupt circuit control register ch.2/ch.3	R/W	00000000$_B$
004A$_H$	EIC20	External interrupt circuit control register ch.4/ch.5	R/W	00000000$_B$
004B$_H$	EIC30	External interrupt circuit control register ch.6/ch.7	R/W	00000000$_B$
004C$_H$ to 004F$_H$	—	(Disabled)	—	—
0050$_H$	SCR	LIN-UART serial control register	R/W	00000000$_B$
0051$_H$	SMR	LIN-UART serial mode register	R/W	00000000$_B$
0052$_H$	SSR	LIN-UART serial status register	R/W	00001000$_B$
0053$_H$	RDR/TDR	LIN-UART reception/transmission data register	R/W	00000000$_B$
0054$_H$	ESCR	LIN-UART extended status control register	R/W	00000100$_B$
0055$_H$	ECCR	LIN-UART extended communication control register	R/W	000000XX$_B$
0056$_H$	SMC10	UART/SIO serial mode control register 1 ch.0	R/W	00000000$_B$
0057$_H$	SMC20	UART/SIO serial mode control register 2 ch.0	R/W	00100000$_B$
0058$_H$	SSR0	UART/SIO serial status register ch.0	R/W	00000001$_B$

(Continued)

Address	Register abbreviation	Register name	R/W	Initial value
0059H	TDR0	UART/SIO serial output data register ch.0	R/W	00000000B
005AH	RDR0	UART/SIO serial input data register ch.0	R	00000000B
005BH to 005FH	—	(Disabled)	—	—
0060H	IBCR00	I²C bus control register 0 ch.0	R/W	00000000B
0061H	IBCR10	I²C bus control register 1 ch.0	R/W	00000000B
0062H	IBSR0	I²C bus status register ch.0	R	00000000B
0063H	IDDR0	I²C data register ch.0	R/W	00000000B
0064H	IAAR0	I²C address register ch.0	R/W	00000000B
0065H	ICCR0	I²C clock control register ch.0	R/W	00000000B
0066H to 006BH	—	(Disabled)	—	—
006CH	ADC1	8/10-bit A/D converter control register 1	R/W	00000000B
006DH	ADC2	8/10-bit A/D converter control register 2	R/W	00000000B
006EH	ADDH	8/10-bit A/D converter data register (upper byte)	R/W	00000000B
006FH	ADDL	8/10-bit A/D converter data register (lower byte)	R/W	00000000B
0070H	WCSR	Watch counter status register	R/W	00000000B
0071H	—	(Disabled)	—	—
0072H	FSR	Flash memory status register	R/W	000X0000B
0073H	SWRE0	Flash memory sector writing control register 0	R/W	00000000B
0074H	SWRE1	Flash memory sector writing control register 1	R/W	00000000B
0075H	—	(Disabled)	—	—
0076H	WREN	Wild register address compare enable register	R/W	00000000B
0077H	WROR	Wild register data test setting register	R/W	00000000B
0078H	—	Register bank pointer (RP) , Mirror of direct bank pointer (DP)	—	—
0079H	ILR0	Interrupt level setting register 0	R/W	11111111B
007AH	ILR1	Interrupt level setting register 1	R/W	11111111B
007BH	ILR2	Interrupt level setting register 2	R/W	11111111B
007CH	ILR3	Interrupt level setting register 3	R/W	11111111B
007DH	ILR4	Interrupt level setting register 4	R/W	11111111B
007EH	ILR5	Interrupt level setting register 5	R/W	11111111B
007FH	—	(Disabled)	—	—
0F80H	WRARH0	Wild register address setting register (upper byte) ch.0	R/W	00000000B

(Continued)

Address	Register abbreviation	Register name	R/W	Initial value
0F81H	WRARL0	Wild register address setting register (lower byte) ch.0	R/W	00000000B
0F82H	WRDR0	Wild register data setting register ch.0	R/W	00000000B
0F83H	WRARH1	Wild register address setting register (upper byte) ch.1	R/W	00000000B
0F84H	WRARL1	Wild register address setting register (lower byte) ch.1	R/W	00000000B
0F85H	WRDR1	Wild register data setting register ch.1	R/W	00000000B
0F86H	WRARH2	Wild register address setting register (upper byte) ch.2	R/W	00000000B
0F87H	WRARL2	Wild register address setting register (lower byte) ch.2	R/W	00000000B
0F88H	WRDR2	Wild register data setting register ch.2	R/W	00000000B
0F89H to 0F91H	—	(Disabled)	—	—
0F92H	T01CR0	8/16-bit compound timer 01 control status register 0 ch.0	R/W	00000000B
0F93H	T00CR0	8/16-bit compound timer 00 control status register 0 ch.0	R/W	00000000B
0F94H	T01DR	8/16-bit compound timer 01 data register ch.0	R/W	00000000B
0F95H	T00DR	8/16-bit compound timer 00 data register ch.0	R/W	00000000B
0F96H	TMCR0	8/16-bit compound timer 00/01 timer mode control register ch.0	R/W	00000000B
0F97H	T11CR0	8/16-bit compound timer 11 control status register 0 ch.1	R/W	00000000B
0F98H	T10CR0	8/16-bit compound timer 10 control status register 0 ch.1	R/W	00000000B
0F99H	T11DR	8/16-bit compound timer 11 data register ch.1	R/W	00000000B
0F9AH	T10DR	8/16-bit compound timer 10 data register ch.1	R/W	00000000B
0F9BH	TMCR1	8/16-bit compound timer 10/11 timer mode control register ch.1	R/W	00000000B
0F9CH	PPS01	8/16-bit PPG1 cycle setting buffer register ch.0	R/W	11111111B
0F9DH	PPS00	8/16-bit PPG0 cycle setting buffer register ch.0	R/W	11111111B
0F9EH	PDS01	8/16-bit PPG1 duty setting buffer register ch.0	R/W	11111111B
0F9FH	PDS00	8/16-bit PPG0 duty setting buffer register ch.0	R/W	11111111B
0FA0H	PPS11	8/16-bit PPG1 cycle setting buffer register ch.1	R/W	11111111B
0FA1H	PPS10	8/16-bit PPG0 cycle setting buffer register ch.1	R/W	11111111B
0FA2H	PDS11	8/16-bit PPG1 duty setting buffer register ch.1	R/W	11111111B
0FA3H	PDS10	8/16-bit PPG0 duty setting buffer register ch.1	R/W	11111111B
0FA4H	PPGS	8/16-bit PPG start register	R/W	00000000B
0FA5H	REVC	8/16-bit PPG output inversion register	R/W	00000000B
0FA6H to 0FA9H	—	(Disabled)	—	—

(Continued)

Address	Register abbreviation	Register name	R/W	Initial value
0FAA$_H$	PDCRH0	16-bit PPG down counter register (upper byte) ch.0	R	00000000$_B$
0FAB$_H$	PDCRL0	16-bit PPG down counter register (lower byte) ch.0	R	00000000$_B$
0FAC$_H$	PCSRH0	16-bit PPG cycle setting buffer register (upper byte) ch.0	R/W	11111111$_B$
0FAD$_H$	PCSRL0	16-bit PPG cycle setting buffer register (lower byte) ch.0	R/W	11111111$_B$
0FAE$_H$	PDUTH0	16-bit PPG duty setting buffer register (upper byte) ch.0	R/W	11111111$_B$
0FAF$_H$	PDUTL0	16-bit PPG duty setting buffer register (lower byte) ch.0	R/W	11111111$_B$
0FB0$_H$ to 0FBB$_H$	—	(Disabled)	—	—
0FBC$_H$	BGR1	LIN-UART baud rate generator register 1	R/W	00000000$_B$
0FBD$_H$	BGR0	LIN-UART baud rate generator register 0	R/W	00000000$_B$
0FBE$_H$	PSSR0	UART/SIO dedicated baud rate generator prescaler selecting register ch.0	R/W	00000000$_B$
0FBF$_H$	BRSR0	UART/SIO dedicated baud rate generator setting register ch.0	R/W	00000000$_B$
0FC0$_H$ to 0FC2$_H$	—	(Disabled)	—	—
0FC3$_H$	AIDRL	A/D input disable register (lower byte)	R/W	00000000$_B$
0FC4$_H$	LCDCC	LCDC control register	R/W	00010000$_B$
0FC5$_H$	LCDCE1	LCDC enable register 1	R/W	00110000$_B$
0FC6$_H$	LCDCE2	LCDC enable register 2	R/W	00000000$_B$
0FC7$_H$	LCDCE3	LCDC enable register 3	R/W	00000000$_B$
0FC8$_H$	LCDCE4	LCDC enable register 4	R/W	00000000$_B$
0FC9$_H$	LCDCE5	LCDC enable register 5	R/W	00000000$_B$
0FCA$_H$	—	(Disabled)	—	—
0FCB$_H$	LCDCB1	LCDC blinking setting register 1	R/W	00000000$_B$
0FCC$_H$	LCDCB2	LCDC blinking setting register 2	R/W	00000000$_B$
0FCD$_H$ to 0FDC$_H$	LCDRAM	LCDC display RAM	R/W	00000000$_B$
0FDD$_H$ to 0FE2$_H$	—	(Disabled)	—	—
0FE3$_H$	WCDR	Watch counter data register	R/W	00111111$_B$

(Continued)

(Continued)

Address	Register abbreviation	Register name	R/W	Initial value
0FE4H to 0FE6H	—	(Disabled)	—	—
0FE7H	ILSR2	Input level select register 2	R/W	00000000B
0FE8H, 0FE9H	—	(Disabled)	—	—
0FEAH	CSVCR	Clock supervisor control register	R/W	00011100B
0FEBH to 0FEDH	—	(Disabled)	—	—
0FEEH	ILSR	Input level selecting register	R/W	00000000B
0FEFH	WICR	Interrupt pin control register	R/W	01000000B
0FF0H to 0FFFH	—	(Disabled)	—	—

- R/W access symbols
  - R/W : Readable/Writable
  - R : Read only
  - W : Write only

- Initial value symbols
  - 0 : The initial value of this bit is “0”.
  - 1 : The initial value of this bit is “1”.
  - X : The initial value of this bit is undefined.

Note : Do not write to the “ (Disabled) ”. Reading the “ (Disabled) ” returns an undefined value.

■ INTERRUPT SOURCE TABLE

Interrupt source	Interrupt request number	Vector table address		Bit name of interrupt level setting register	Same level priority order (at simultaneous occurrence)
		Upper	Lower		
External interrupt ch.0	IRQ0	FFFA$_H$	FFFB$_H$	L00 [1 : 0]	High
External interrupt ch.4					
External interrupt ch.1	IRQ1	FFF8$_H$	FFF9$_H$	L01 [1 : 0]	
External interrupt ch.5					
External interrupt ch.2	IRQ2	FFF6$_H$	FFF7$_H$	L02 [1 : 0]	
External interrupt ch.6					
External interrupt ch.3	IRQ3	FFF4$_H$	FFF5$_H$	L03 [1 : 0]	
External interrupt ch.7					
UART/SIO ch.0	IRQ4	FFF2$_H$	FFF3$_H$	L04 [1 : 0]	
8/16-bit compound timer ch.0 (Lower)	IRQ5	FFF0$_H$	FFF1$_H$	L05 [1 : 0]	
8/16-bit compound timer ch.0 (Upper)	IRQ6	FFEE$_H$	FFEF$_H$	L06 [1 : 0]	
LIN-UART (reception)	IRQ7	FFEC$_H$	FFED$_H$	L07 [1 : 0]	
LIN-UART (transmission)	IRQ8	FFEA$_H$	FFEB$_H$	L08 [1 : 0]	
8/16-bit PPG ch.1 (Lower)	IRQ9	FFE8$_H$	FFE9$_H$	L09 [1 : 0]	
8/16-bit PPG ch.1 (Upper)	IRQ10	FFE6$_H$	FFE7$_H$	L10 [1 : 0]	
(Unused)	IRQ11	FFE4$_H$	FFE5$_H$	L11 [1 : 0]	
8/16-bit PPG ch.0 (Upper)	IRQ12	FFE2$_H$	FFE3$_H$	L12 [1 : 0]	
8/16-bit PPG ch.0 (Lower)	IRQ13	FFE0$_H$	FFE1$_H$	L13 [1 : 0]	
8/16-bit compound timer ch.1 (Upper)	IRQ14	FFDE$_H$	FFDF$_H$	L14 [1 : 0]	
16-bit PPG ch.0	IRQ15	FFDC$_H$	FFDD$_H$	L15 [1 : 0]	
I^2C ch.0	IRQ16	FFDA$_H$	FFDB$_H$	L16 [1 : 0]	
(Unused)	IRQ17	FFD8$_H$	FFD9$_H$	L17 [1 : 0]	
8/10-bit A/D converter	IRQ18	FFD6$_H$	FFD7$_H$	L18 [1 : 0]	
Time-base timer	IRQ19	FFD4$_H$	FFD5$_H$	L19 [1 : 0]	
Watch prescaler/Watch counter	IRQ20	FFD2$_H$	FFD3$_H$	L20 [1 : 0]	
(Unused)	IRQ21	FFD0$_H$	FFD1$_H$	L21 [1 : 0]	
8/16-bit compound timer ch.1 (Lower)	IRQ22	FFCE$_H$	FFCF$_H$	L22 [1 : 0]	
Flash memory	IRQ23	FFCC$_H$	FFCD$_H$	L23 [1 : 0]	Low

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

Parameter	Symbol	Rating		Unit	Remarks
		Min	Max		
Power supply voltage*1	V_{CC}, AV_{CC}	Vss – 0.3	Vss + 6.0	V	*2
	AVR	Vss – 0.3	Vss + 6.0		*2
Power supply voltage for LCD	V0 to V3	Vss – 0.3	Vss + 6.0	V	*3
Input voltage*1	V_I	Vss – 0.3	Vss + 6.0	V	*4
Output voltage*1	V_O	Vss – 0.3	Vss + 6.0	V	*4
Maximum clamp current	I_{CLAMP}	– 2.0	+ 2.0	mA	Applicable to pins*5
Total maximum clamp current	$\Sigma\lvert I_{CLAMP}\rvert$	—	20	mA	Applicable to pins*5
“L” level maximum output current	I_{OL}	—	15	mA	Applicable to pins*5
“L” level average current	I_{OLAV}	—	4	mA	Applicable to pins*5 Average output current = operating current × operating ratio (1 pin)
“L” level total maximum output current	ΣI_{OL}	—	100	mA	
“L” level total average output current	ΣI_{OLAV}	—	50	mA	Total average output current = operating current × operating ratio (Total of pins)
“H” level maximum output current	I_{OH}	—	– 15	mA	Applicable to pins*5
“H” level average current	I_{OHAV}	—	– 4	mA	Applicable to pins*5 Average output current = operating current × operating ratio (1 pin)
“H” level total maximum output current	ΣI_{OH}	—	– 100	mA	
“H” level total average output current	ΣI_{OHAV}	—	– 50	mA	Total average output current = operating current × operating ratio (Total of pins)
Power consumption	Pd	—	320	mW	
Operating temperature	T_A	– 40	+ 85	°C	
Storage temperature	Tstg	– 55	+ 150	°C	

(Continued)

(Continued)

*1 : The parameter is based on V_{SS} = 0.0 V.

*2 : Apply equal potential to AV_{CC} and V_{CC}. AVR should not exceed AV_{CC} + 0.3 V.

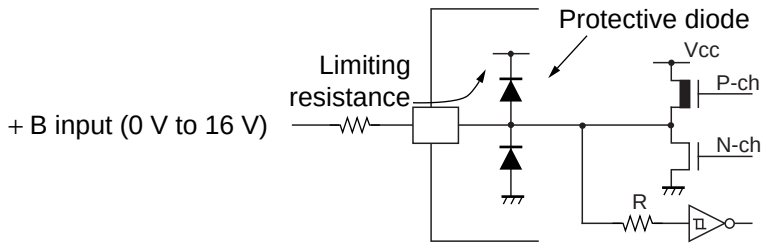
*3 : V0 to V3 should not exceed V_{CC} + 0.3 V.

*4 : V_I and Vo should not exceed V_{CC} + 0.3 V. V_I must not exceed the rating voltage. However, if the maximum current to/from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_I rating.

*5 : Applicable to pins :
P00 to P07, P10 to P14, P20 to P22,P60 to P67, P90 to P95, PA0 to PA3, PB0 to PB7, PC0 to PC7

- Use within recommended operating conditions.
- Use at DC voltage (current).
- + B signal is an input signal that exceeds V_{CC} voltage. The + B signal should always be applied a limiting resistance placed between the + B signal and the microcontroller.
- The value of the limiting resistance should be set so that when the + B signal is applied the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
- Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the V_{CC} pin, and this affects other devices.
- Note that if the + B signal is inputted when the microcontroller power supply is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
- Note that if the + B input is applied during power-on, the power supply is provided from the pins and the resulting power supply voltage may not be sufficient to operate the power-on reset.
- Care must be taken not to leave the + B input pin open.
- Note that analog system input/output pins other than the A/D input pins (LCD drive pins, etc.) cannot accept + B signal input.
- Sample recommended circuits :

- Input/Output Equivalent circuits



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

2. Recommended Operating Conditions

(Vss = 0.0 V)

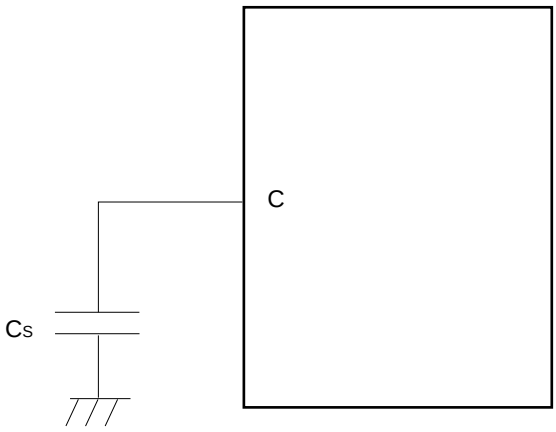
Parameter	Symbol	Condi-tions	Value		Unit	Remarks	
			Min	Max			
Power supply voltage	V_{CC}, AV_{CC}	—	2.42*1,*2	5.5*1	V	In normal operating	Other than MB95FV100D-103
			2.3	5.5		Hold condition in STOP mode	
			2.7	5.5		In normal operating	MB95FV100D-103
			2.3	5.5		Hold condition in STOP mode	
Power supply voltage for LCD	V0 to V3		V_{SS}	V_{CC}	V	The range of liquid crystal power supply (The optimal value depends on liquid crystal display elements used.)	
A/D converter reference input voltage	AVR		4.0	AV_{CC}	V		
Smoothing capacitor	C_S		0.1	1.0	µF	*3	
Operating temperature	T_A		– 40	+ 85	°C	Other than MB95FV100D-103	
			+ 5	+35	°C	MB95FV100D-103	

*1 : The values vary with the operating frequency, machine clock or analog guarantee range.

*2 : When the low voltage detection reset is used, reset occurs while the low voltage is detected. For details on Low voltage detection, see "(9) Low Voltage Detection" in "4. AC Characteristics ".

*3 : Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. A bypass capacitor of V_{CC} pin must have a capacitor value higher than C_S. For connection of smoothing capacitor C_S, refer to the diagram below.

• C pin connection diagram



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

3. DC Characteristics

(Vcc = 5.0 V ± 10%, Vss = 0.0 V, T_A = − 40 °C to + 85 °C)

Parameter	Sym-bol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
"H" level input voltage	V_{IH1}	P10, P67	*1	0.7 V_{CC}	—	V_{CC} + 0.3	V	When selecting CMOS input level
	V_{IH2}	P23, P24	*1	0.7 V_{CC}	—	V_{SS} + 5.5	V	
	V_{IHA}	P00 to P07, P10 to P14, P20 to P22, P60 to P67, P90 to P95, PA0 to PA3, PB0 to PB7, PC0 to PC7	—	0.8 V_{CC}	—	V_{CC} + 0.3	V	Port inputs if Auto-motive input levels are selected
	V_{IHS1}	P00 to P07, P10 to P14, P20 to P22, P60 to P67, P90 to P95, PA0 to PA3, PB0 to PB7, PC0 to PC7	*1	0.8 V_{CC}	—	V_{CC} + 0.3	V	Hysteresis input
	V_{IHS2}	P23, P24	*1	0.8 V_{CC}	—	V_{SS} + 5.5	V	
	V_{IHM}	$\overline{RST}$, MOD	—	0.8 V_{CC}	—	V_{CC} + 0.3	V	
"L" level input voltage	V_{IL}	P10,P23, P24,P67	*1	V_{SS} − 0.3	—	0.3 V_{CC}	V	Hysteresis input (When selecting CMOS input level)
	V_{ILA}	P00 to P07, P10 to P14, P20 to P24, P60 to P67, P90 to P95, PA0 to PA3, PB0 to PB7, PC0 to PC7	—	V_{SS} − 0.3	—	0.5 V_{CC}	V	Port inputs if Automotive input levels are selected
	V_{ILS}	P00 to P07, P10 to P14, P20 to P24, P60 to P67, P90 to P95, PA0 to PA3, PB0 to PB7, PC0 to PC7	*1	V_{SS} − 0.3	—	0.2 V_{CC}	V	Hysteresis input
	V_{ILM}	$\overline{RST}$, MOD	—	V_{SS} − 0.3	—	0.3 V_{CC}	V	Hysteresis input
"H" level output voltage	V_{OH}	All output pins	I_{OH} = − 4.0 mA	V_{cc} − 0.5	—	—	V	
"L" level output voltage	V_{OL}	$\overline{RST}$*2, All output pins	I_{OL} = 4.0 mA	—	—	0.4	V	

(Continued)

(Vcc = 5.0 V ± 10%, Vss = 0.0 V, T_A = – 40 °C to + 85 °C)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Input leakage current (Hi-Z output leakage current)	I_{LI}	Ports other than P23, P24	0.0 V < V_I < V_{CC}	– 5	—	+ 5	µA	When the pull-up prohibition setting
Open drain output leakage current	I_{LIOD}	P23, P24	0.0 V < V_I < V_{SS} + 5.5 V	—	—	5	µA	
Pull-up resistor	R_{PULL}	P10 to P14, P20 to P22	V_I = 0.0 V	25	50	100	kΩ	When the pull-up permission setting
Pull-down resistor	R_{MOD}	MOD	V_I = V_{CC}	50	100	200	kΩ	Mask ROM product only
Input capacitance	C_{IN}	Other than AV_{CC}, AV_{SS}, AVR, V_{CC}, V_{SS}	f = 1 MHz	—	5	15	pF	
Power supply current*3	I_{CC}	V_{CC} (External clock operation)	F_{CH} = 20 MHz F_{MP} = 10 MHz Main clock mode (divided by 2)	—	9.5	12.5	mA	Flash memory product (At other than Flash memory writing and erasing)
				—	30.0	35.0	mA	Flash memory product (At Flash memory writing and erasing)
				—	7.2	9.5	mA	Mask ROM product
			F_{CH} = 32 MHz F_{MP} = 16 MHz Main clock mode (divided by 2)	—	15.2	20.0	mA	Flash memory product (At other than Flash memory writing and erasing)
				—	35.7	42.5	mA	Flash memory product (At Flash memory writing and erasing)
				—	11.6	15.2	mA	Mask ROM product
	I_{CCS}		F_{CH} = 20 MHz F_{MP} = 10 MHz Main Sleep mode (divided by 2)	—	4.5	7.5	mA	
			F_{CH} = 32 MHz F_{MP} = 16 MHz Main Sleep mode (divided by 2)	—	7.2	12.0	mA	

(Continued)

(Vcc = 5.0 V ± 10%, Vss = 0.0 V, T_A = − 40 °C to + 85 °C)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current*3	I_{CCL}	V_{CC} (External clock operation)	F_{CL} = 32 kHz F_{MPL} = 16 kHz Sub clock mode (divided by 2) T_A = + 25 °C	—	45	100	µA	
	I_{CCLS}		F_{CL} = 32 kHz F_{MPL} = 16 kHz Sub sleep mode (divided by 2) T_A = + 25 °C	—	10	81	µA	
	I_{CCT}		F_{CL} = 32 kHz Watch mode Main stop mode T_A = + 25 °C	—	4.6	27.0	µA	
	I_{CCMPLL}		F_{CH} = 4 MHz F_{MP} = 10 MHz Main PLL mode (multiplied by 2.5)	—	9.3	12.5	mA	Flash memory product
				—	7	9.5	mA	Mask ROM product
			F_{CH} = 6.4 MHz F_{MP} = 16 MHz Main PLL mode (multiplied by 2.5)	—	14.9	20.0	mA	Flash memory product
				—	11.2	15.2	mA	Mask ROM product
	I_{CCSPLL}		F_{CL} = 32 kHz F_{MPL} = 128 kHz Sub PLL mode (multiplied by 4), T_A = + 25 °C	—	160	400	µA	
	I_{CTS}		F_{CH} = 10 MHz Time-base timer mode T_A = + 25 °C	—	0.15	1.10	mA	
	I_{CCH}		Sub stop mode T_A = + 25 °C	—	5	20	µA	
	I_A	AV_{CC}	F_{CH} = 16 MHz At operating of A/D conversion	—	2.4	4.7	mA	
	I_{AH}		F_{CH} = 16 MHz At stopping of A/D conversion T_A = + 25 °C	—	1	5	µA	
LCD internal division resistance	R_{LCD}	—	Between V3 and V_{SS}	—	300	—	kΩ	
COM0 to COM3 output impedance	R_{VCOM}	COM0 to COM3	V1 to V3 = 5.0 V	—	—	5	kΩ	
SEG00 to SEG31 output impedance	R_{VSEG}	SEG00 to SEG31		—	—	7	kΩ	

(Continued)

(Continued)

Parameter	Sym-bol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
LCD leak current	I_{LCDL}	V0 to V3, COM0 to COM3 SEG00 to SEG31	—	− 1	—	+ 1	µA	

*1 : The value is 2.88 V when the low voltage detection reset is used.

*2 : Product without clock supervisor only

*3 :
- The power-supply current is determined by the external clock. When both low voltage detection option and clock supervisor option are selected, the power-supply current will be a value of adding current consumption of the low voltage detection circuit (I_{LVD}) and current consumption of built-in CR oscillator (I_{CSV}) to the specified value.
- Refer to “4. AC Characteristics (1) Clock Timing” for F_{CH} and F_{CL}.
- Refer to “4. AC Characteristics (2) Source Clock/Machine Clock” for F_{MP} and F_{MPL}.

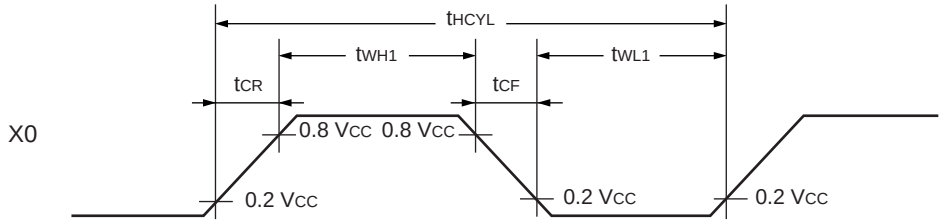
4. AC Characteristics

(1) Clock Timing

(Vcc = 2.42 V to 5.5 V, Vss = 0.0 V, T_A = − 40 °C to + 85 °C)

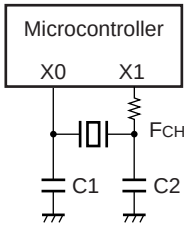
Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Clock frequency	F_{CH}	X0, X1	—	1.00	—	16.25	MHz	When using main oscillation circuit
				1.00	—	32.50	MHz	When using external clock
				3.00	—	10.00	MHz	Main PLL multiplied by 1
				3.00	—	8.13	MHz	Main PLL multiplied by 2
				3.00	—	6.50	MHz	Main PLL multiplied by 2.5
				3.00	—	4.06	MHz	Main PLL multiplied by 4
	F_{CL}	X0A, X1A		—	32.768	—	kHz	When using sub oscillation circuit
				—	32.768	—	kHz	When using sub PLL
Clock cycle time	t_{HCYL}	X0, X1		61.5	—	1000	ns	When using oscillation circuit
				30.8	—	1000	ns	When using external clock
	t_{LCYL}	X0A, X1A		—	30.5	—	µs	When using sub clock
Input clock pulse width	t_{WH1} t_{WL1}	X0		61.5	—	—	ns	When using external clock Duty ratio is about 30% to 70%.
	t_{WH2} t_{WL2}	X0A		—	15.2	—	µs	
Input clock rise time and fall time	t_{CR} t_{CF}	X0, X0A		—	—	5	ns	When using external clock

• Input wave form for using external clock (main clock)

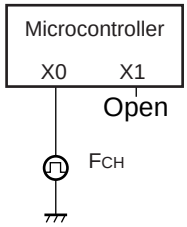


• Figure of Main Clock Input Port External Connection

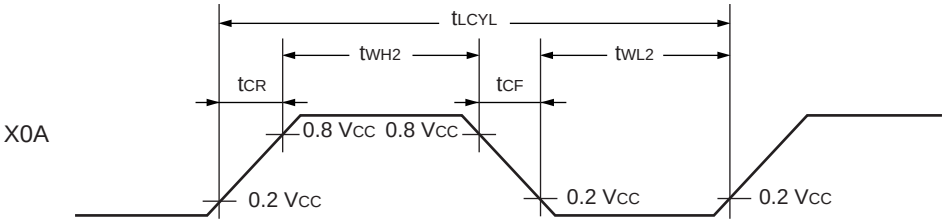
When using a crystal or ceramic oscillator



When using external clock

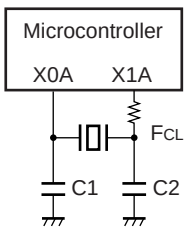


• Input wave form for using external clock (sub clock)

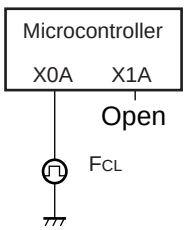


• Figure of Sub clock Input Port External Connection

When using a crystal or ceramic oscillator



When using external clock



(2) Source Clock/Machine Clock

(Vcc = 5.0 V ± 10%, Vss = 0.0 V, T_A = − 40 °C to + 85 °C)

Parameter	Sym-bol	Condi-tions	Value			Unit	Remarks
			Min	Typ	Max		
Source clock cycle time*1 (Clock before setting division)	t_{SCLK}	—	61.5	—	2000	ns	When using main clock Min : F_{CH} = 8.125 MHz, PLL multiplied by 2 Max : F_{CH} = 1 MHz, divided by 2
			7.6	—	61.0	µs	When using sub clock Min : F_{CL} = 32 kHz, PLL multiplied by 4 Max : F_{CL} = 32 kHz, divided by 2
Source clock frequency	F_{SP}		0.50	—	16.25	MHz	When using main clock
	F_{SPL}		16.384	—	131.072	kHz	When using sub clock
Machine clock cycle time*2 (Minimum instruction execution time)	t_{MCLK}		61.5	—	32000	ns	When using main clock Min : F_{SP} = 16.25 MHz, no division Max : F_{SP} = 0.5 MHz, divided by 16
			7.6	—	976.5	µs	When using sub clock Min : F_{SPL} = 131 kHz, no division Max : F_{SPL} = 16 kHz, divided by 16
Machine clock frequency	F_{MP}		0.031	—	16.250	MHz	When using main clock
	F_{MPL}		1.024	—	131.072	kHz	When using sub clock

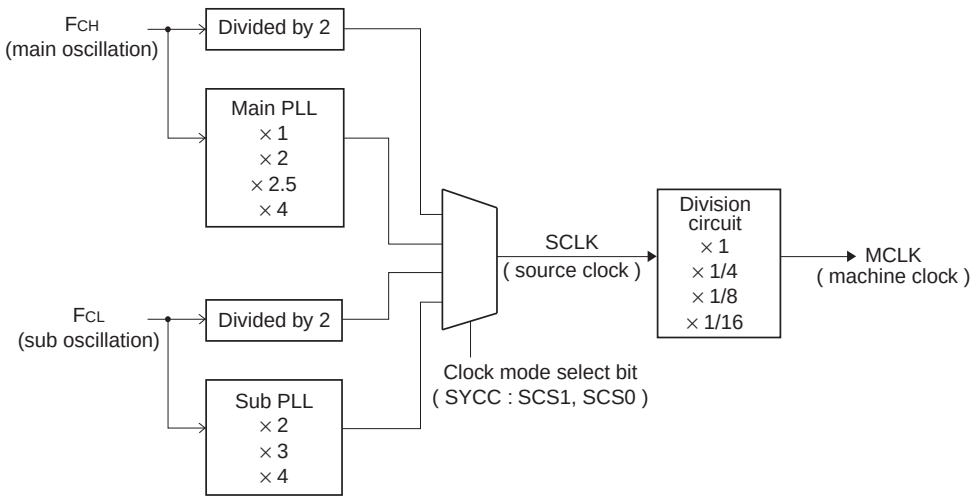
*1 : Clock before setting division due to machine clock division ratio selection bit (SYCC : DIV1 and DIV0) . This source clock is divided by the machine clock division ratio selection bit (SYCC : DIV1 and DIV0) , and it becomes the machine clock. Further, the source clock can be selected as follows.

- Main clock divided by 2
- PLL multiplication of main clock (select from 1, 2, 2.5, 4 multiplication)
- Sub clock divided by 2
- PLL multiplication of sub clock (select from 2, 3, 4 multiplication)

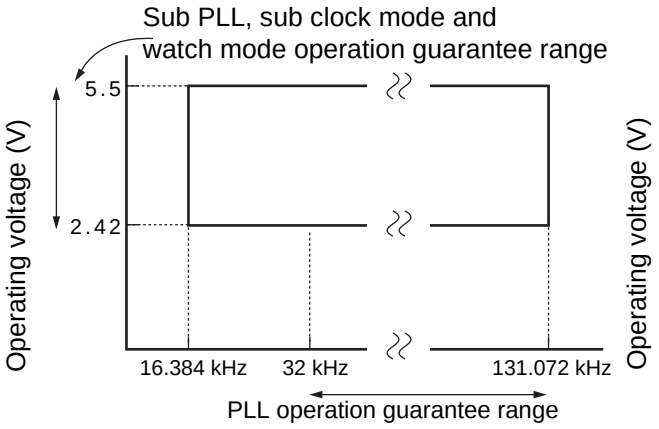
*2 : Operation clock of the microcontroller. Machine clock can be selected as follows.

- Source clock (no division)
- Source clock divided by 4
- Source clock divided by 8
- Source clock divided by 16

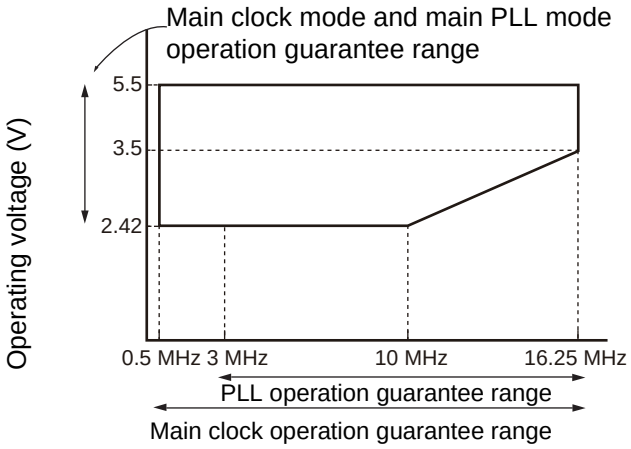
• Outline of clock generation block



- Operating voltage - Operating frequency (When T_A = − 40 °C to + 85 °C)
  - MB95168MA/F168MA/F168NA/F168JA

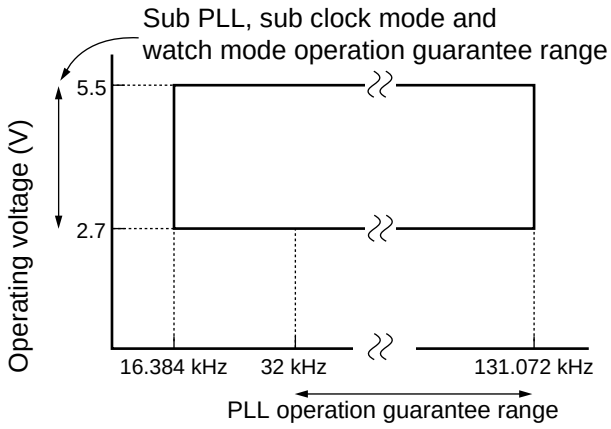


Source clock frequency (F_{SPL})

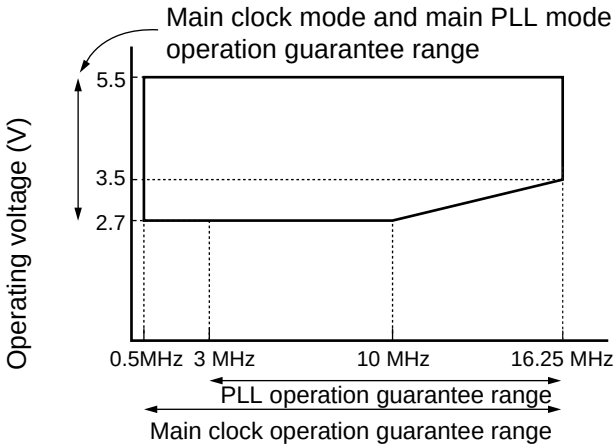


Source clock frequency (F_{SP})

- Operating voltage - Operating frequency (When T_A = + 5 °C to + 35 °C)
  - MB95FV100D-103

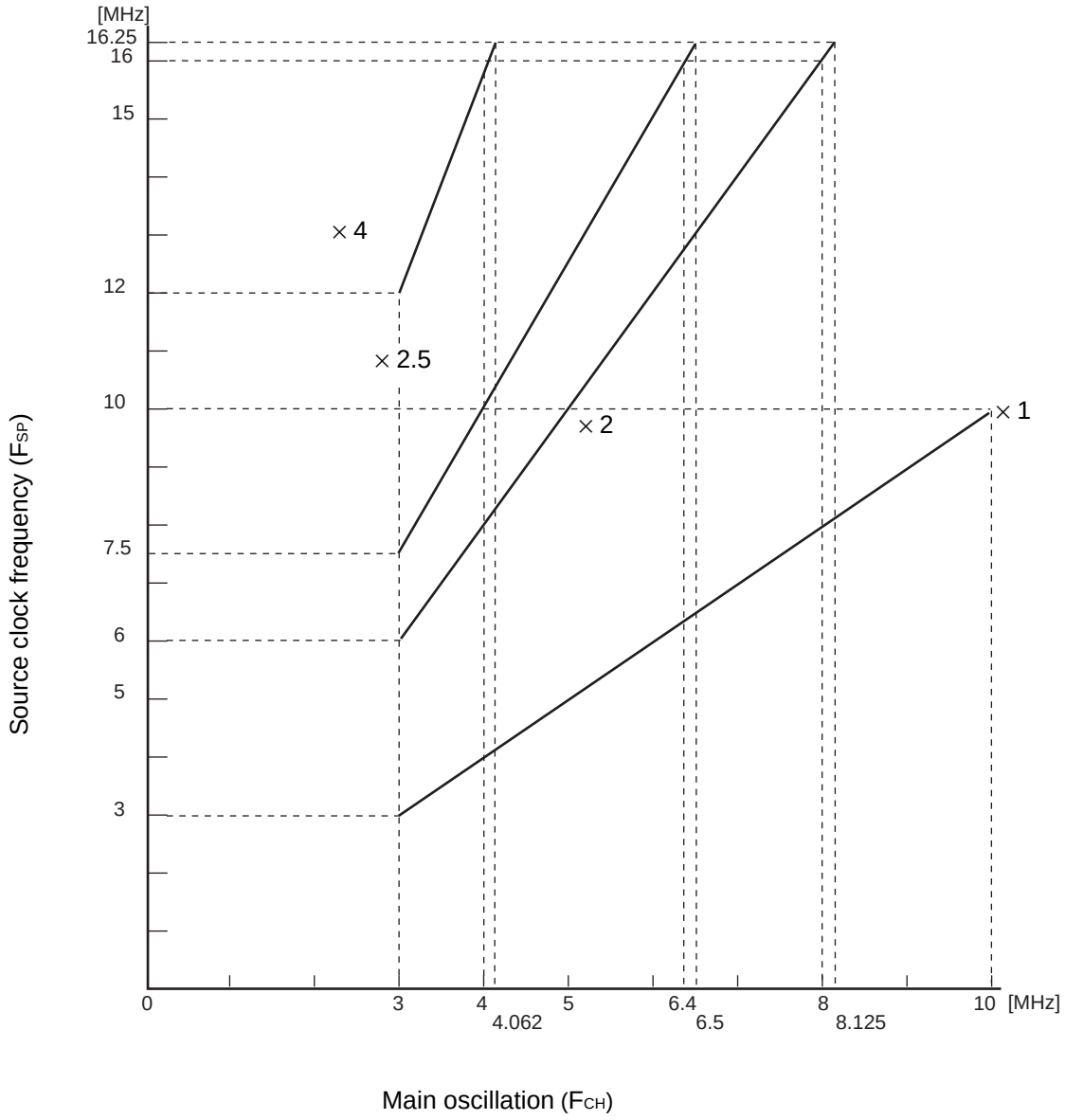


Source clock frequency (F_{SPL})



Source clock frequency (F_{SP})

• Main PLL operation frequency



(3) External Reset

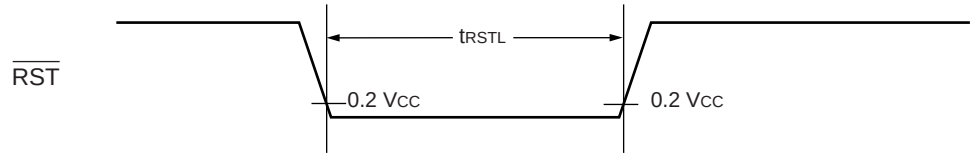
(Vcc = 5.0 V ± 10%, Vss = 0.0 V, T_A = − 40 °C to + 85 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
$\overline{RST}$ "L" level pulse width	t_{RSTL}	$\overline{RST}$	—	2 t_{MCLK}*1	—	ns	At normal operating
				Oscillation time of oscillator*2 + 100	—	µs	At stop mode, sub clock mode, sub sleep mode, and watch mode
				100	—	µs	At time-base timer mode

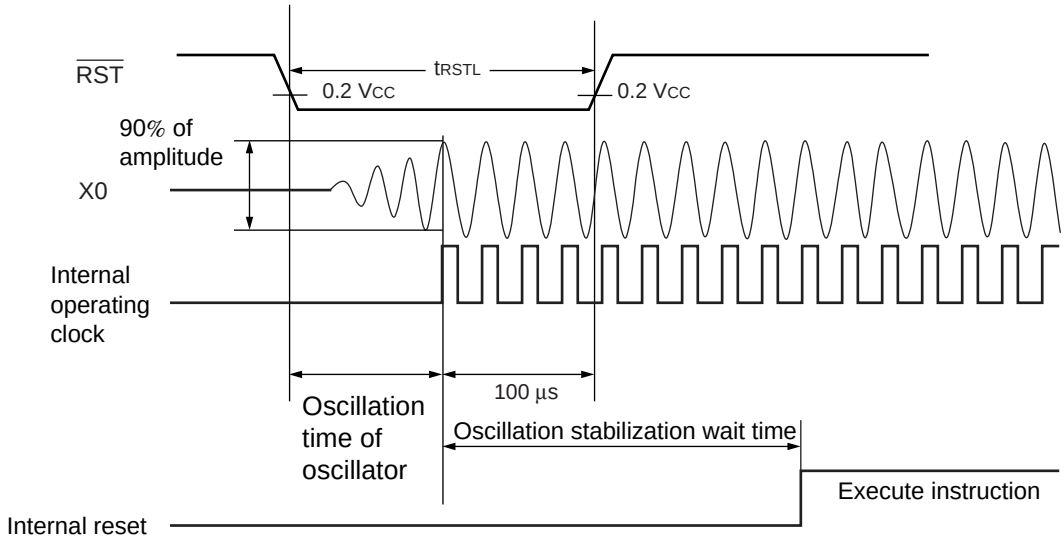
*1 : Refer to " (2) Source Clock/Machine Clock" for t_{MCLK}.

*2 : Oscillation time of oscillator is the time that the amplitude reaches 90%. In the crystal oscillator, the oscillation time is between several ms and tens of ms. In ceramic oscillators, the oscillation time is between hundreds of µs and several ms. In the external clock, the oscillation time is 0 ms.

• At normal operating



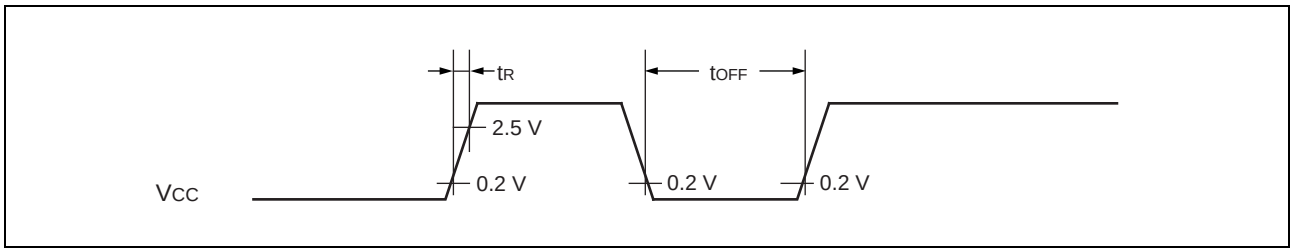
• At stop mode, sub clock mode, sub sleep mode, watch mode, and power-on



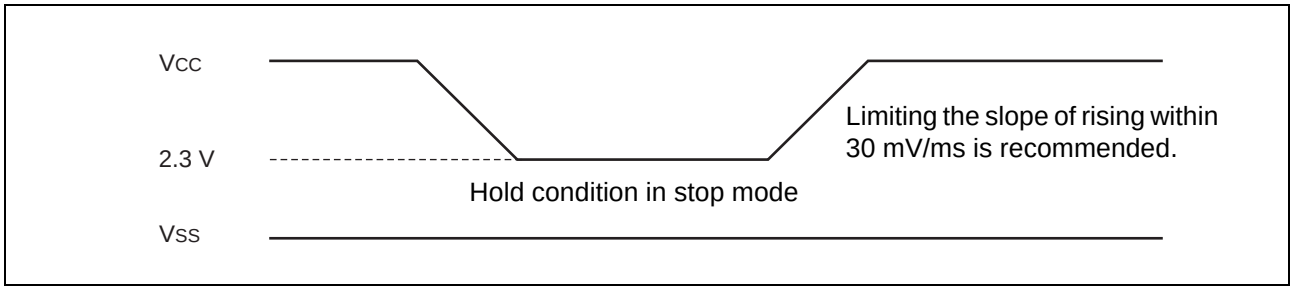
(4) Power-on Reset

(Vss = 0.0 V, T_A = − 40 °C to + 85 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Power supply rising time	t_R	V_{CC}	—	—	50	ms	
Power supply cutoff time	t_{OFF}			1	—	ms	Waiting time until power-on



Note : Sudden change of power supply voltage may activate the power-on reset function. When changing power supply voltages during operation, set the slope of rising within 30 mV/ms as shown below.

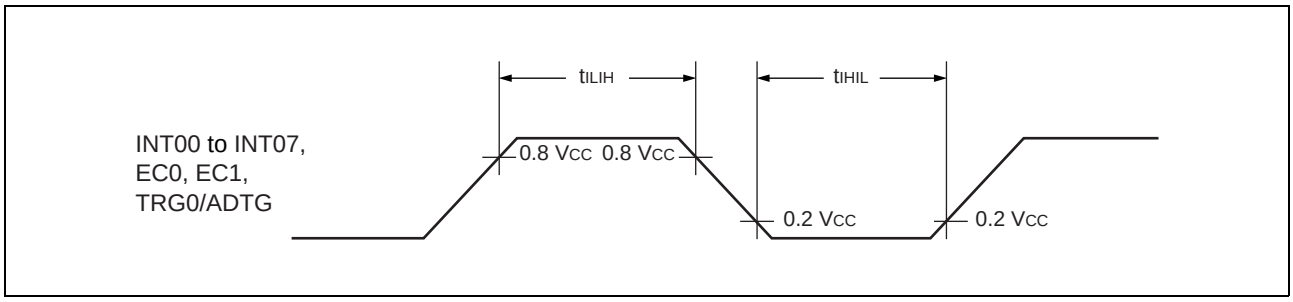


(5) Peripheral Input Timing

(Vcc = 5.0 V ± 10%, Vss = 0.0 V, T_A = − 40 °C to + 85 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Peripheral input “H” pulse width	t_{ILIH}	INT00 to INT07, EC0, EC1, TRG0/ADTG	—	2 t_{MCLK}*	—	ns
Peripheral input “L” pulse width	t_{IHIL}			2 t_{MCLK}*	—	ns

* : Refer to “ (2) Source Clock/Machine Clock” for t_{MCLK}.



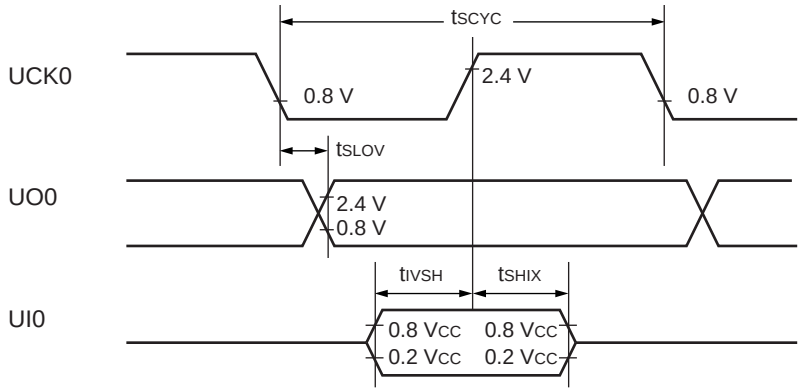
(6) UART/SIO, Serial I/O Timing

(Vcc = 5.0 V ± 10%, Vss = 0.0 V, T_A = − 40 °C to + 85 °C)

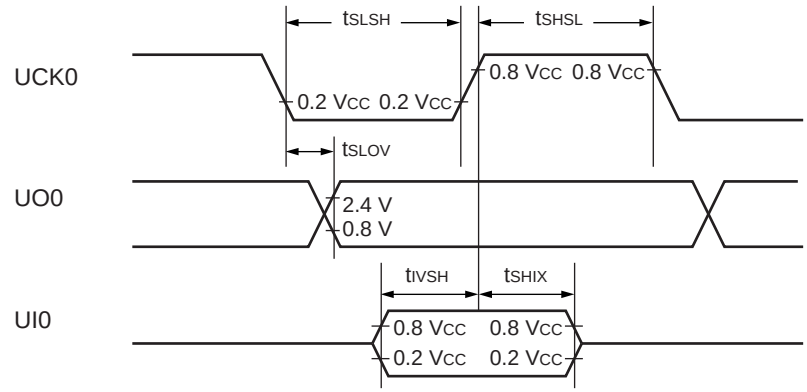
Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	UCK0	Internal clock operation output pin : C_L = 80 pF + 1TTL.	4 t_{MCLK}*	—	ns
UCK ↓ → UO time	t_{SLOV}	UCK0, UO0		− 190	+ 190	ns
Valid UI → UCK ↑	t_{IVSH}	UCK0, UI0		2 t_{MCLK}*	—	ns
UCK ↑ → valid UI hold time	t_{SHIX}	UCK0, UI0		2 t_{MCLK}*	—	ns
Serial clock “H” pulse width	t_{SHSL}	UCK0	External clock operation output pin : C_L = 80 pF + 1TTL.	4 t_{MCLK}*	—	ns
Serial clock “L” pulse width	t_{SLSH}	UCK0		4 t_{MCLK}*	—	ns
UCK ↓ → UO time	t_{SLOV}	UCK0, UO0		—	190	ns
Valid UI → UCK ↑	t_{IVSH}	UCK0, UI0		2 t_{MCLK}*	—	ns
UCK ↑ → valid UI hold time	t_{SHIX}	UCK0, UI0		2 t_{MCLK}*	—	ns

* : Refer to “ (2) Source Clock/Machine Clock” for t_{MCLK}.

• Internal shift clock mode



• External shift clock mode



(7) LIN-UART Timing

Sampling at the rising edge of sampling clock*1 and prohibited serial clock delay*2
(ESCR register : SCES bit = 0, ECCR register : SCDE bit = 0)

(Vcc = 5.0 V ± 10%, Vss = 0.0 V, T_A = –40 °C to + 85 °C)

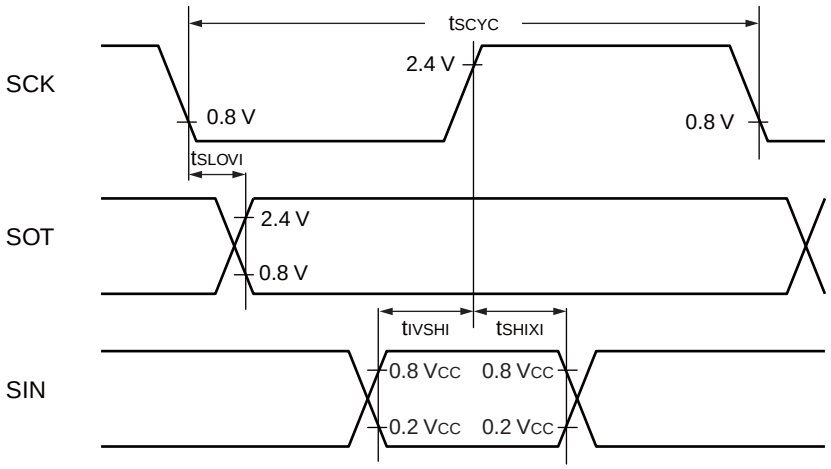
Parameter	Sym-bol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK	Internal clock operation output pin : C_L = 80 pF + 1 TTL.	5 t_{MCLK}*3	—	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCK, SOT		–95	+ 95	ns
Valid SIN → SCK ↑	t_{IVSHI}	SCK, SIN		t_{MCLK}*3 + 190	—	ns
SCK ↑ → valid SIN hold time	t_{SHIXI}	SCK, SIN		0	—	ns
Serial clock “L” pulse width	t_{SLSH}	SCK	External clock operation output pin : C_L = 80 pF + 1 TTL.	3 t_{MCLK}*3 – t_R	—	ns
Serial clock “H” pulse width	t_{SHSL}	SCK		t_{MCLK}*3 + 95	—	ns
SCK ↓ → SOT delay time	t_{SLOVE}	SCK, SOT		—	2 t_{MCLK}*3 + 95	ns
Valid SIN → SCK ↑	t_{IVSHE}	SCK, SIN		190	—	ns
SCK ↑ → valid SIN hold time	t_{SHIXE}	SCK, SIN		t_{MCLK}*3 + 95	—	ns
SCK fall time	t_F	SCK		—	10	ns
SCK rise time	t_R	SCK		—	10	ns

*1 : Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

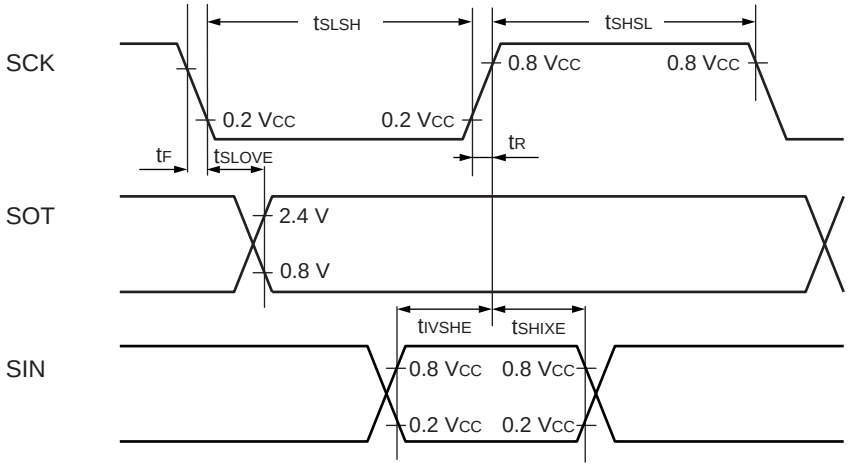
*2 : Serial clock delay function is used to delay half clock for the output signal of serial clock.

*3 : Refer to “ (2) Source Clock/Machine Clock” for t_{MCLK}.

- Internal shift clock mode



- External shift clock mode



Sampling at the falling edge of sampling clock*1 and prohibited serial clock delay*2
(ESCR register : SCES bit = 1, ECCR register : SCDE bit = 0)

(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = –40 °C to + 85 °C)

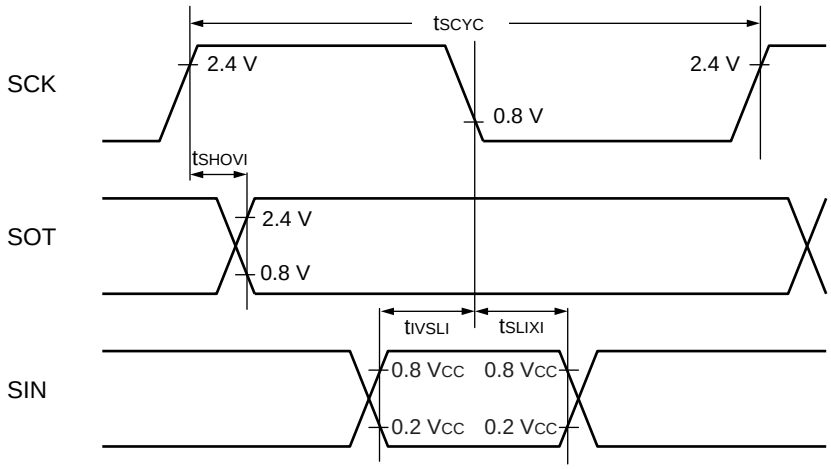
Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK	Internal clock operation output pin : C_L = 80 pF + 1 TTL.	5 t_{MCLK}*3	—	ns
SCK↑→ SOT delay time	t_{SHOVI}	SCK, SOT		–95	+ 95	ns
Valid SIN→SCK↓	t_{IVSLI}	SCK, SIN		t_{MCLK}*3 + 190	—	ns
SCK↓→ valid SIN hold time	t_{SLIXI}	SCK, SIN		0	—	ns
Serial clock “H” pulse width	t_{SHSL}	SCK	External clock operation output pin : C_L = 80 pF + 1 TTL.	3 t_{MCLK}*3 – t_R	—	ns
Serial clock “L” pulse width	t_{SLSH}	SCK		t_{MCLK}*3 + 95	—	ns
SCK↑ →SOT delay time	t_{SHOVE}	SCK, SOT		—	2 t_{MCLK}*3 + 95	ns
Valid SIN→SCK↓	t_{IVSLE}	SCK, SIN		190	—	ns
SCK↓→ valid SIN hold time	t_{SLIXE}	SCK, SIN		t_{MCLK}*3 + 95	—	ns
SCK fall time	t_F	SCK		—	10	ns
SCK rise time	t_R	SCK		—	10	ns

*1 : Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

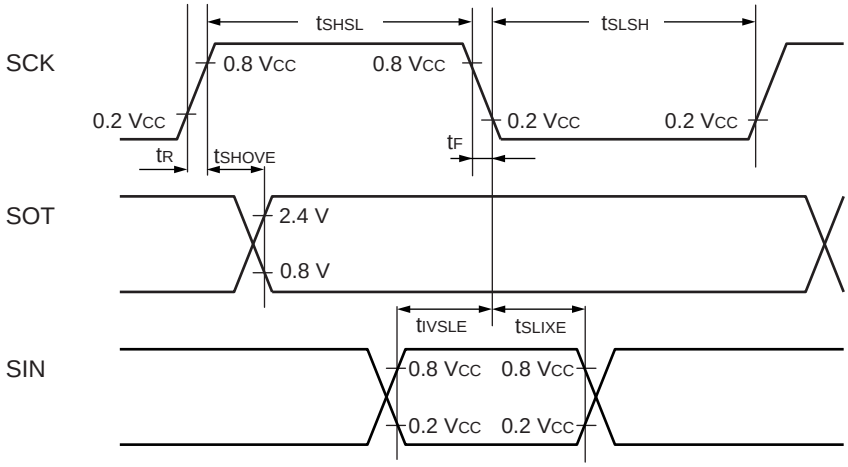
*2 : Serial clock delay function is used to delay half clock for the output signal of serial clock.

*3 : Refer to “ (2) Source Clock/Machine Clock” for t_{MCLK}.

- Internal shift clock mode



- External shift clock mode



Sampling at the rising edge of sampling clock*1 and enabled serial clock delay*2
(ESCR register : SCES bit = 0, ECCR register : SCDE bit = 1)

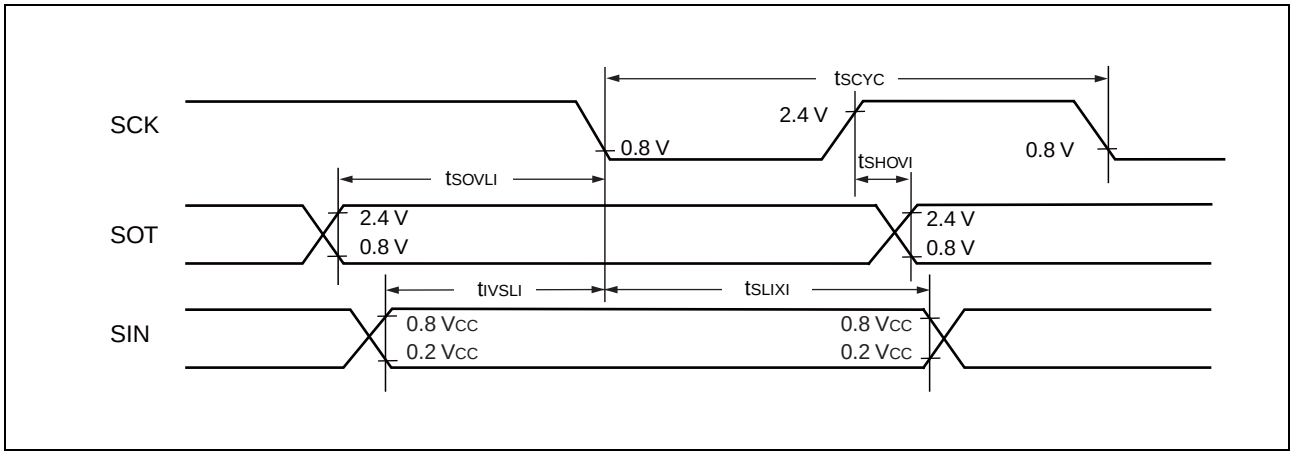
(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = –40 °C to + 85 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK	Internal clock operation output pin : C_L = 80 pF + 1 TTL.	5 t_{MCLK}*3	—	ns
SCK↑→ SOT delay time	t_{SHOVI}	SCK, SOT		–95	+ 95	ns
Valid SIN→SCK↓	t_{IVSLI}	SCK, SIN		t_{MCLK}*3 + 190	—	ns
SCK↓→ valid SIN hold time	t_{SLIXI}	SCK, SIN		0	—	ns
SOT→SCK↓ delay time	t_{SOVLI}	SCK, SOT		—	4 t_{MCLK}*3	ns

*1 : Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

*2 : Serial clock delay function is used to delay half clock for the output signal of serial clock.

*3 : Refer to " (2) Source Clock/Machine Clock" for t_{MCLK}.



Sampling at the falling edge of sampling clock*1 and enabled serial clock delay*2
(ESCR register : SCES bit = 1, ECCR register : SCDE bit = 1)

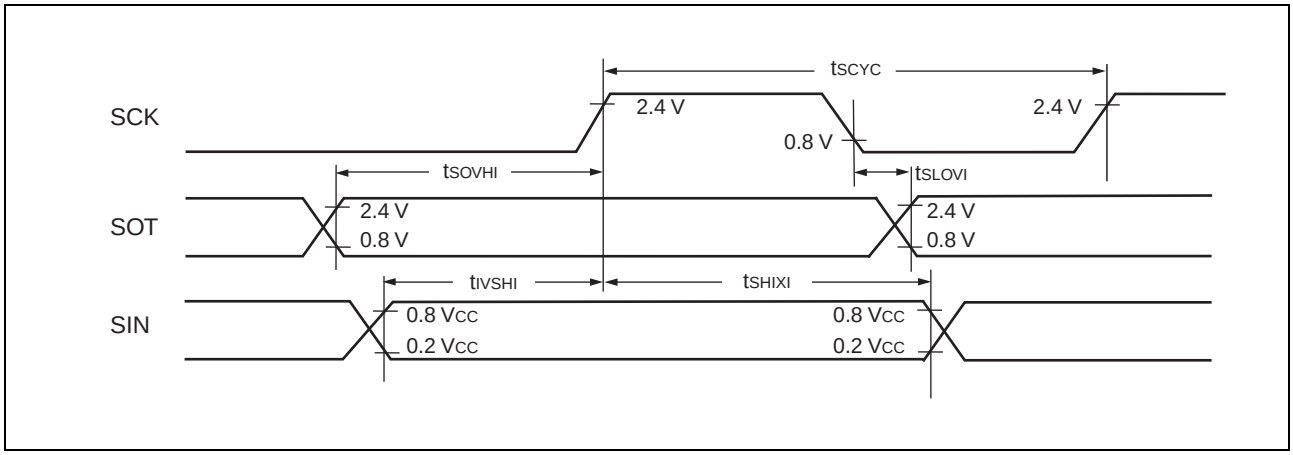
(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = –40 °C to + 85 °C)

Parameter	Sym-bol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK	Internal clock operation output pin : C_L = 80 pF + 1 TTL.	5 t_{MCLK}*3	—	ns
SCK↓→SOT delay time	t_{SLOVI}	SCK, SOT		–95	+ 95	ns
Valid SIN→SCK↑	t_{IVSHI}	SCK, SIN		t_{MCLK}*3 + 190	—	ns
SCK↑ → valid SIN hold time	t_{SHIXI}	SCK, SIN		0	—	ns
SOT→SCK↑ delay time	t_{SOVHI}	SCK, SOT		—	4 t_{MCLK}*3	ns

*1 : Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

*2 : Serial clock delay function is used to delay half clock for the output signal of serial clock.

*3 : Refer to " (2) Source Clock/Machine Clock" for t_{MCLK}.



(8) I²C Timing

(V_{CC} = 5.0 V ± 10%, AV_{SS} = V_{SS} = 0.0 V, T_A = − 40 °C to + 85 °C)

Parameter	Symbol	Pin name	Conditions	Value				Unit
				Standard-mode		Fast-mode		
				Min	Max	Min	Max	
SCL clock frequency	f_{SCL}	SCL0	R = 1.7 kΩ, C = 50 pF*1	0	100	0	400	kHz
(Repeat) Start condition hold time SDA ↓ → SCL ↓	$t_{HD;STA}$	SCL0 SDA0		4.0	—	0.6	—	µs
SCL clock “L” width	t_{LOW}	SCL0		4.7	—	1.3	—	µs
SCL clock “H” width	t_{HIGH}	SCL0		4.0	—	0.6	—	µs
(Repeat) Start condition setup time SCL ↑ → SDA ↓	$t_{SU;STA}$	SCL0 SDA0		4.7	—	0.6	—	µs
Data hold time SCL ↓ → SDA ↓ ↑	$t_{HD;DAT}$	SCL0 SDA0		0	3.45*2	0	0.9*3	µs
Data setup time SDA ↓ ↑ → SCL ↑	$t_{SU;DAT}$	SCL0 SDA0		0.25*4	—	0.1*4	—	µs
Stop condition setup time SCL ↑ → SDA ↑	$t_{SU;STO}$	SCL0 SDA0		4.0	—	0.6	—	µs
Bus free time between stop condition and start condition	t_{BUF}	SCL0 SDA0		4.7	—	1.3	—	µs

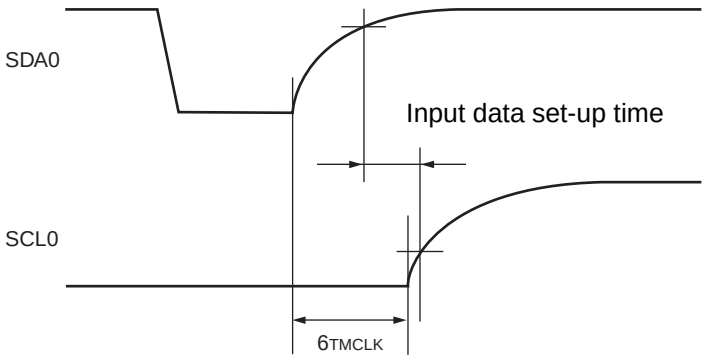
*1 : R, C : Pull-up resistor and load capacitor of the SCL and SDA lines.

*2 : The maximum $t_{HD;DAT}$ have only to be met if the device dose not stretch the “L” width (t_{LOW}) of the SCL signal.

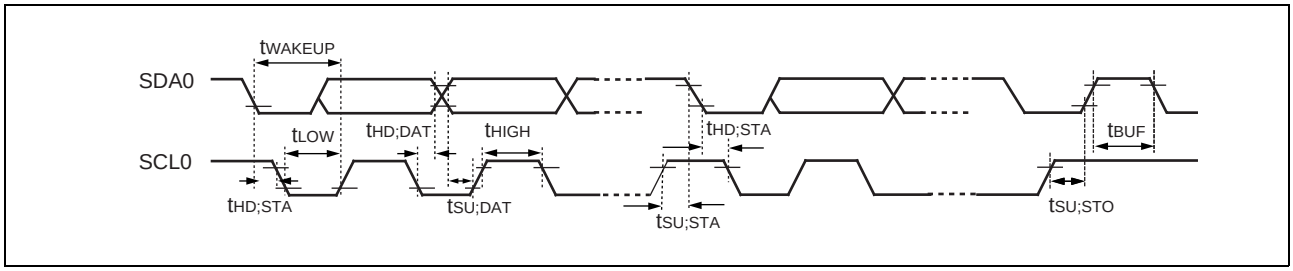
*3 : A fast-mode I²C-bus device can be used in a standard-mode I²C-bus system, but the requirement $t_{SU;DAT} \geq$ 250 ns must then be met.

*4 : Refer to “ • Note of SDA and SCL set-up time”.

• Note of SDA and SCL set-up time



The rating of the input data set-up time in the device connected to the bus cannot be satisfied depending on the load capacitance or pull-up resistor.
Be sure to adjust the pull-up resistor of SDA and SCL if the rating of the input data set-up time cannot be satisfied.


SDA0
SCL0
tWAKEUP
tLOW
tHD;DAT
tHIGH
tHD;STA
tBUF
tHD;STA
tSU;DAT
tSU;STA
tSU;STO

(V_{CC} = 5.0 V ± 10%, AV_{SS} = V_{SS} = 0.0 V, T_A = –40 °C to + 85 °C)

Parameter	Symbol	Pin name	Conditions	Value*2		Unit	Remarks
				Min	Max		
SCL clock “L” width	t_{LOW}	SCL0	R = 1.7 kΩ, C = 50 pF*1	(2 + nm / 2) t_{MCLK} – 20	—	ns	Master mode
SCL clock “H” width	t_{HIGH}	SCL0		(nm / 2) t_{MCLK} – 20	(nm / 2) t_{MCLK} + 20	ns	Master mode
Start condition hold time	$t_{HD;STA}$	SCL0 SDA0		(–1 + nm / 2) t_{MCLK} – 20	(–1 + nm) t_{MCLK} + 20	ns	Master mode Maximum value is applied when m, n = 1, 8. Otherwise, the minimum value is applied.
Stop condition setup time	$t_{SU;STO}$	SCL0 SDA0		(1 + nm / 2) t_{MCLK} – 20	(1 + nm / 2) t_{MCLK} + 20	ns	Master mode
Start condition setup time	$t_{SU;STA}$	SCL0 SDA0		(1 + nm / 2) t_{MCLK} – 20	(1 + nm / 2) t_{MCLK} + 20	ns	Master mode
Bus free time between stop condition and start condition	t_{BUF}	SCL0 SDA0		(2 nm + 4) t_{MCLK} – 20	—	ns	
Data hold time	$t_{HD;DAT}$	SCL0 SDA0		3 t_{MCLK} – 20	—	ns	Master mode
Data setup time	$t_{SU;DAT}$	SCL0 SDA0		(–2 + nm / 2) t_{MCLK} – 20	(–1 + nm / 2) t_{MCLK} + 20	ns	Master mode When assuming that “L” of SCL is not extended, the minimum value is applied to first bit of continuous data. Otherwise, the maximum value is applied.
Setup time between clearing interrupt and SCL rising	$t_{SU;INT}$	SCL0		(nm / 2) t_{MCLK} – 20	(1 + nm / 2) t_{MCLK} + 20	ns	Minimum value is applied to interrupt at 9th SCL↓. Maximum value is applied to interrupt at 8th SCL↓.
SCL clock “L” width	t_{LOW}	SCL0		4 t_{MCLK} – 20	—	ns	At reception
SCL clock “H” width	t_{HIGH}	SCL0		4 t_{MCLK} – 20	—	ns	At reception
Start condition detection	$t_{HD;STA}$	SCL0 SDA0		2 t_{MCLK} – 20	—	ns	Undetected when 1 t_{MCLK} is used at reception

(Continued)

(Continued)

(V_{CC} = 5.0 V ± 10%, AV_{SS} = V_{SS} = 0.0 V, T_A = –40 °C to + 85 °C)

Parameter	Symbol	Pin name	Conditions	Value*2		Unit	Remarks
				Min	Max		
Stop condition detection	$t_{SU;STO}$	SCL0 SDA0	R = 1.7 kΩ, C = 50 pF*1	2 t_{MCLK} – 20	—	ns	Undetected when 1 t_{MCLK} is used at reception
Restart condition detection condition	$t_{SU;STA}$	SCL0 SDA0		2 t_{MCLK} – 20	—	ns	Undetected when 1 t_{MCLK} is used at reception
Bus free time	t_{BUF}	SCL0 SDA0		2 t_{MCLK} – 20	—	ns	At reception
Data hold time	$t_{HD;DAT}$	SCL0 SDA0		2 t_{MCLK} – 20	—	ns	At slave transmission mode
Data setup time	$t_{SU;DAT}$	SCL0 SDA0		t_{LOW} – 3 t_{MCLK} – 20	—	ns	At slave transmission mode
Data hold time	$t_{HD;DAT}$	SCL0 SDA0		0	—	ns	At reception
Data setup time	$t_{SU;DAT}$	SCL0 SDA0		t_{MCLK} – 20	—	ns	At reception
SDA↓→SCL↑ (at wakeup function)	$t_{WAKE-UP}$	SCL0 SDA0		Oscillation stabilization wait time + 2 t_{MCLK} – 20	—	ns	

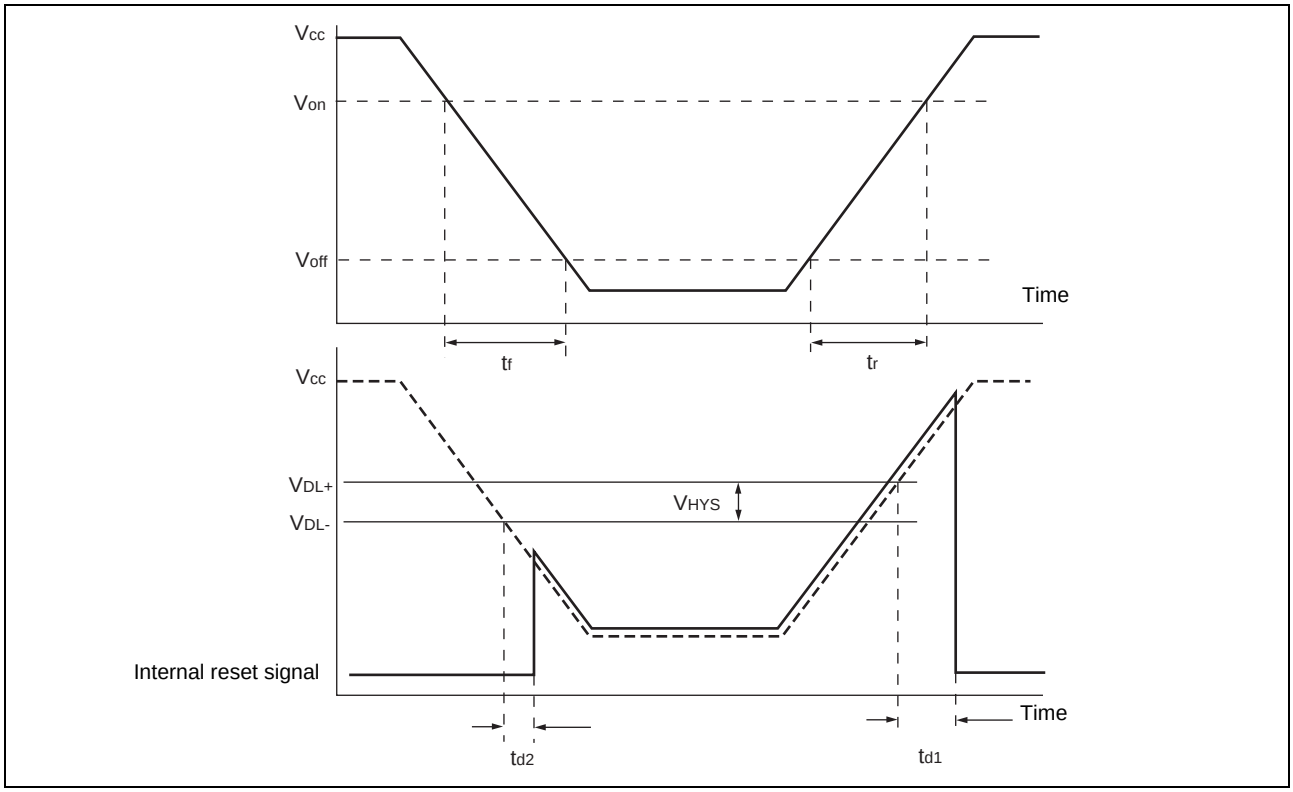
*1 : R, C : Pull-up resistor and load capacitor of the SCL and SDA lines.

*2 : •Refer to " (2) Source Clock/Machine Clock" for t_{MCLK}.
- m is CS4 bit and CS3 bit (bit 4 and bit 3) of I²C clock control register (ICCR) .
- n is CS2 bit to CS0 bit (bit 2 to bit 0) of I²C clock control register (ICCR) .
- Actual timing of I²C is determined by m and n values set by the machine clock (t_{MCLK}) and CS4 to CS0 of ICCR0 register.
- Standard-mode :
  m and n can be set at the range : 0.9 MHz < t_{MCLK} (machine clock) < 10 MHz.
  Setting of m and n determines the machine clock that can be used below.
  (m, n) = (1, 8) : 0.9 MHz < t_{MCLK} ≤ 1 MHz
  (m, n) = (1, 22) , (5, 4) , (6, 4) , (7, 4) , (8, 4) : 0.9 MHz < t_{MCLK} ≤ 2 MHz
  (m, n) = (1, 38) , (5, 8) , (6, 8) , (7, 8) , (8, 8) : 0.9 MHz < t_{MCLK} ≤ 4 MHz
  (m, n) = (1, 98) : 0.9 MHz < t_{MCLK} ≤ 10 MHz
- Fast-mode :
  m and n can be set at the range : 3.3 MHz < t_{MCLK} (machine clock) < 10 MHz.
  Setting of m and n determines the machine clock that can be used below.
  (m, n) = (1, 8) : 3.3 MHz < t_{MCLK} ≤ 4 MHz
  (m, n) = (1, 22) , (5, 4) : 3.3 MHz < t_{MCLK} ≤ 8 MHz
  (m, n) = (6, 4) : 3.3 MHz < t_{MCLK} ≤ 10 MHz

(9) Low Voltage Detection

(Vss = 0.0 V, T_A = –40 °C to + 85 °C)

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Release voltage	V_{DL+}	—	2.52	2.70	2.88	V	At power-supply rise
Detection voltage	V_{DL-}		2.42	2.60	2.78	V	At power-supply fall
Hysteresis width	V_{HYS}		70	100	—	mV	
Power-supply start voltage	V_{off}		—	—	2.3	V	
Power-supply end voltage	V_{on}		4.9	—	—	V	
Power-supply voltage change time (at power supply rise)	t_r		0.3	—	—	µs	Slope of power supply that reset release signal generates
			—	3000	—	µs	Slope of power supply that reset release signal generates within rating (V_{DL+})
Power-supply voltage change time (at power supply fall)	t_f		300	—	—	µs	Slope of power supply that reset detection signal generates
			—	300	—	µs	Slope of power supply that reset detection signal generates within rating (V_{DL-})
Reset release delay time	t_{d1}		—	—	400	µs	
Reset detection delay time	t_{d2}		—	—	30	µs	
Current consumption	I_{LVD}		—	38	50	µA	Current consumption of low voltage detection circuit only



(10) Clock Supervisor Clock

(Vcc = 5.0 V ± 10%, Vss = 0.0 V, T_A = –40 °C to + 85 °C)

Parameter	Symbol	Condi-tions	Value			Unit	Remarks
			Min	Typ	Max		
Oscillation frequency	f_{OUT}	—	50	100	200	kHz	
Oscillation start time	t_{wk}		—	—	10	µs	
Current consumption	I_{CSV}		—	20	36	µA	Current consumption of built-in CR oscillator, at 100 kHz oscillation

5. A/D Converter

(1) A/D Converter Electrical Characteristics

($AV_{CC} = V_{CC}$ = 4.0 V to 5.5 V, $AV_{SS} = V_{SS}$ = 0.0 V, T_A = − 40 °C to + 85 °C)

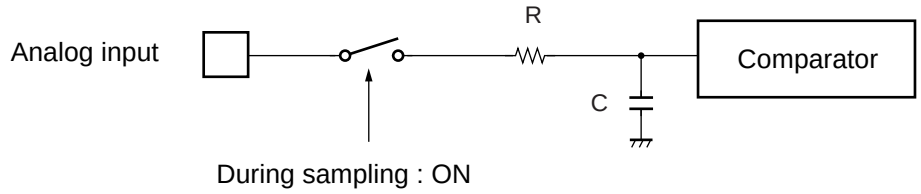
Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	—	—	—	—	10	bit	
Total error			− 3.0	—	+ 3.0	LSB	
Linearity error			− 2.5	—	+ 2.5	LSB	
Differential linear error			− 1.9	—	+ 1.9	LSB	
Zero transition voltage	V_{OT}	—	AV_{SS} − 1.5 LSB	AV_{SS} + 0.5 LSB	AV_{SS} + 2.5 LSB	V	
Full-scale transition voltage	V_{FST}		AVR − 3.5 LSB	AVR − 1.5 LSB	AVR + 0.5 LSB	V	
Compare time	—		0.9	—	16500	µs	4.5 V ≤ AVcc ≤ 5.5 V
			1.8	—	16500	µs	4.0 V ≤ AVcc < 4.5 V
Sampling time	—		0.6	—	∞	µs	4.5 V ≤ AVcc ≤ 5.5 V, At external impedance < 5.4 kΩ
			1.2	—	∞	µs	4.0 V ≤ AVcc < 4.5 V, At external impedance < 2.4 kΩ
Analog input current	I_{AIN}		− 0.3	—	+ 0.3	µA	
Analog input voltage	V_{AIN}		AV_{SS}	—	AVR	V	
Reference voltage	—		AV_{SS} + 4.0	—	AV_{CC}	V	AVR pin
Reference voltage supply current	I_R		—	600	900	µA	AVR pin, during A/D operation
	I_{RH}		—	—	5	µA	AVR pin, at stop mode

(2) Notes on Using A/D Converter

- **About the external impedance of analog input and its sampling time**

A/D converter with sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the internal sample and hold capacitor is insufficient, adversely affecting A/D conversion precision. Therefore, to satisfy the A/D conversion precision standard, consider the relationship between the external impedance and minimum sampling time and either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. Also, if the sampling time cannot be sufficient, connect a capacitor of about 0.1 µF to the analog input pin.

- Analog input equivalent circuit

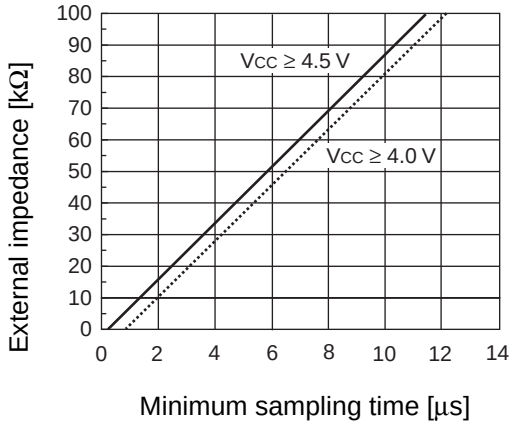


	R	C
4.5 V ≤ V_{CC} ≤ 5.5 V	2.0 kΩ (Max)	16 pF (Max)
4.0 V ≤ V_{CC} < 4.5 V	8.2 kΩ (Max)	16 pF (Max)

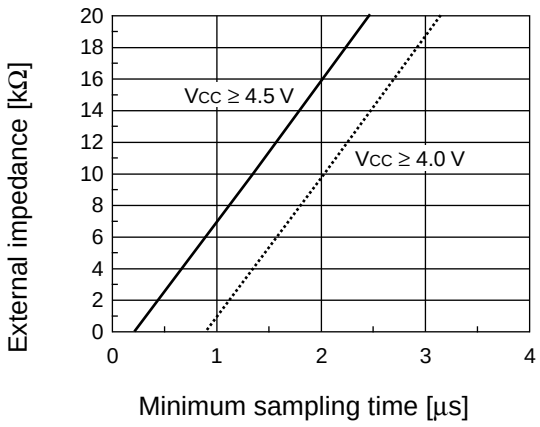
Note : The values are reference values.

- The relationship between external impedance and minimum sampling time

(External impedance = 0 kΩ to 100 kΩ)



(External impedance = 0 kΩ to 20 kΩ)



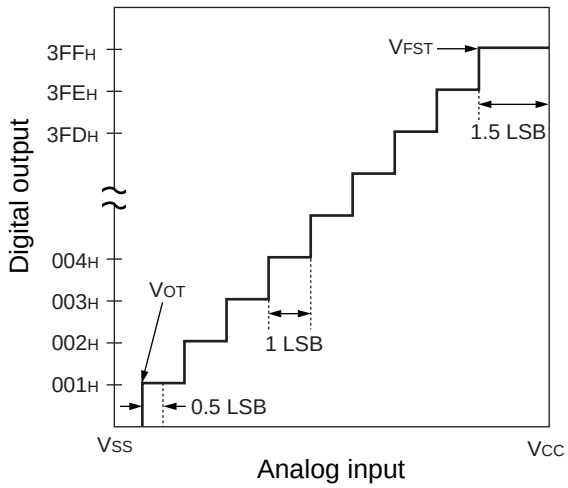
- **About errors**

As |V_{CC} – V_{SS}| becomes smaller, values of relative errors grow larger.

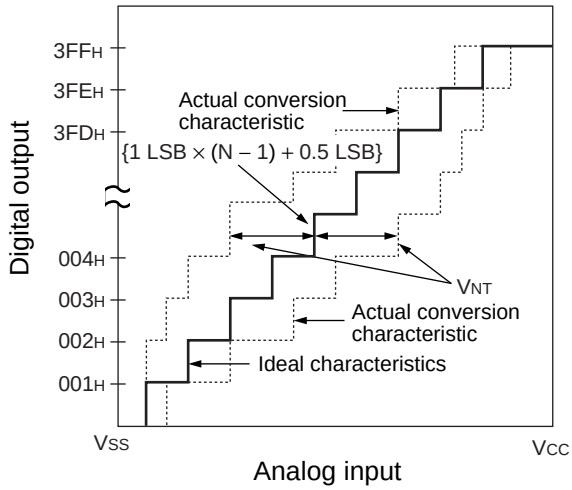
(3) Definition of A/D Converter Terms

- Resolution
  The level of analog variation that can be distinguished by the A/D converter.
  When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.
- Linearity error (unit : LSB)
  The deviation between the value along a straight line connecting the zero transition point (“00 0000 0000” ← → “00 0000 0001”) of a device and the full-scale transition point (“11 1111 1111” ← → “11 1111 1110”) compared with the actual conversion values obtained.
- Differential linear error (Unit : LSB)
  Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.
- Total error (unit: LSB)
  Difference between actual and theoretical values, caused by a zero transition error, full-scale transition error, linearity error, quantum error, and noise.

Ideal I/O characteristics



Total error



$$1\ \text{LSB} = \frac{V_{CC} - Vss}{1024}\ \text{(V)}$$

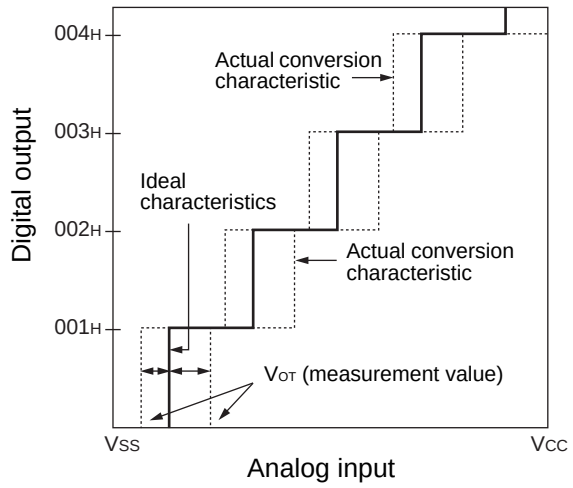
$$\text{Total error of digital output N} = \frac{V_{NT} - \{1\ \text{LSB} \times (N - 1) + 0.5\ \text{LSB}\}}{1\ \text{LSB}}\ \text{[LSB]}$$

N : A/D converter digital output value
V_{NT} : A voltage at which digital output transits from $(N - 1)_H$ to N_H

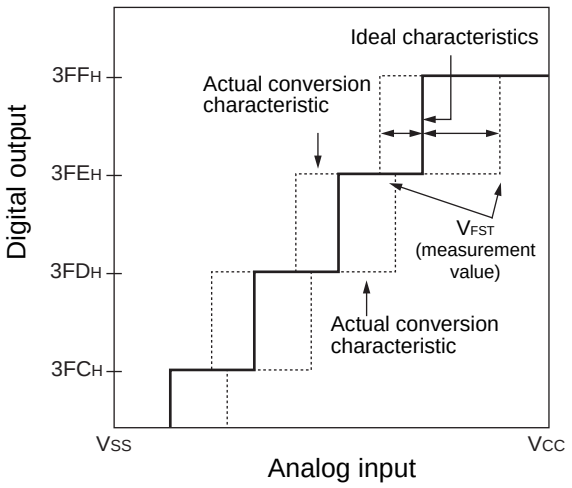
(Continued)

(Continued)

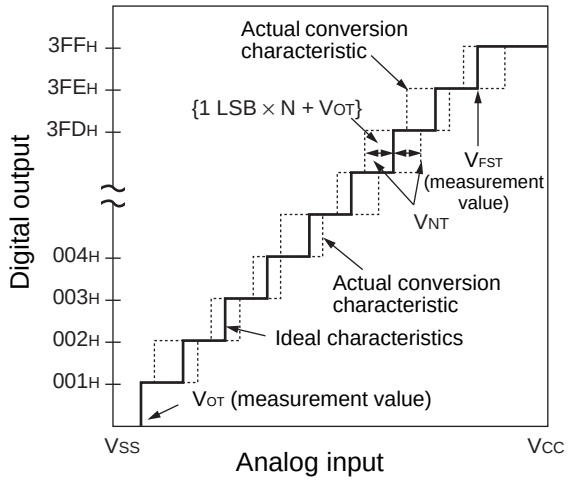
Zero transition error



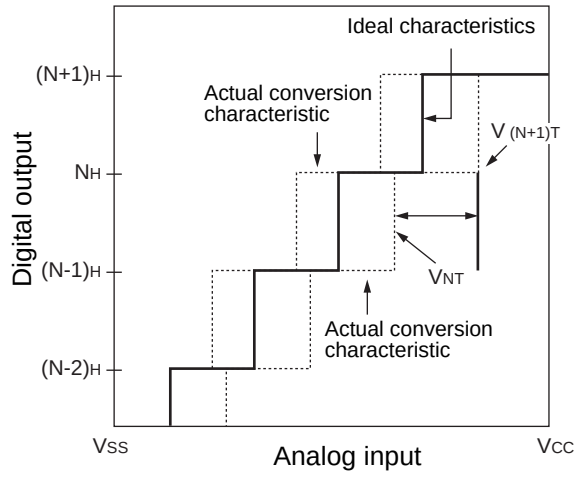
Full-scale transition error



Linearity error



Differential linear error



$$\text{Linearity error in digital output N} = \frac{V_{NT} - \{1\ \text{LSB} \times N + V_{OT}\}}{1\ \text{LSB}}$$

$$\text{Differential linear error in digital output N} = \frac{V_{(N+1)T} - V_{NT}}{1\ \text{LSB}} - 1$$

N : A/D converter digital output value
V_{NT} : A voltage at which digital output transits from (N – 1) H to N_H
V_{OT} (Ideal value) = V_{SS} + 0.5 LSB [V]
V_{FST} (Ideal value) = V_{CC} – 1.5 LSB [V]

6. Flash Memory Program/Erase Characteristics

Parameter	Conditions	Value			Unit	Remarks
		Min	Typ	Max		
Chip erase time	—	—	1*1	15*2	s	Excludes 00_H programming prior erasure.
Byte programming time		—	32	3600	µs	Excludes system-level overhead.
Erase/program cycle		10000	—	—	cycle	
Power supply voltage at erase/program		4.5	—	5.5	V	
Flash memory data retention time		20*3	—	—	year	Average T_A = + 85 °C

*1 : T_A = + 25 °C, V_{CC} = 5.0 V, 10000 cycles

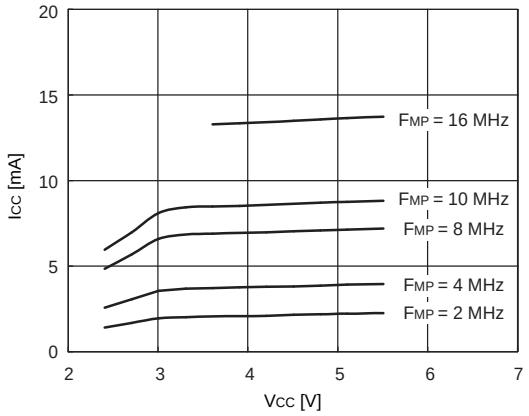
*2 : T_A = + 85 °C, V_{CC} = 4.5 V, 10000 cycles

*3 : This value comes from the technology qualification (using Arrhenius equation to translate high temperature measurements into normalized value at +85 °C) .

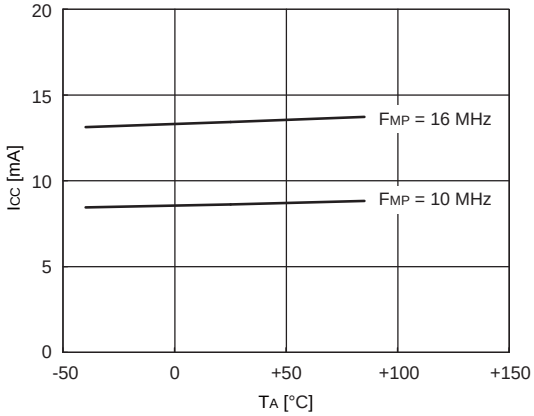
■ EXAMPLE CHARACTERISTICS

• Power supply current temperature (MB95F168MA/F168NA/F168JA)

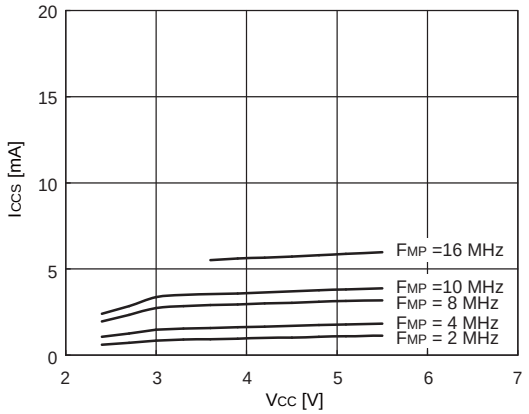
I_{CC} – V_{CC}
T_A = + 25 °C, F_{MP} = 2, 4, 8, 10, 16 MHz (divided by 2)
Main clock mode, at external clock operating



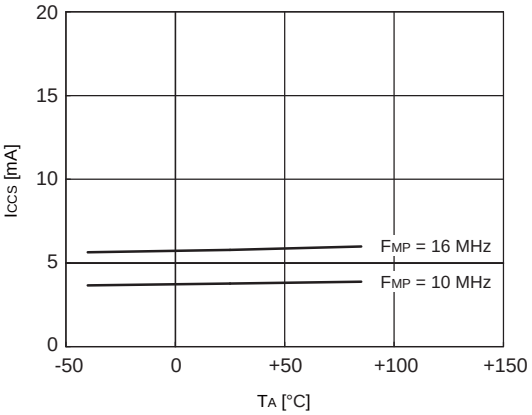
I_{CC} – T_A
V_{CC} = 5.5 V, F_{MP} = 10, 16 MHz (divided by 2)
Main clock mode, at external clock operating



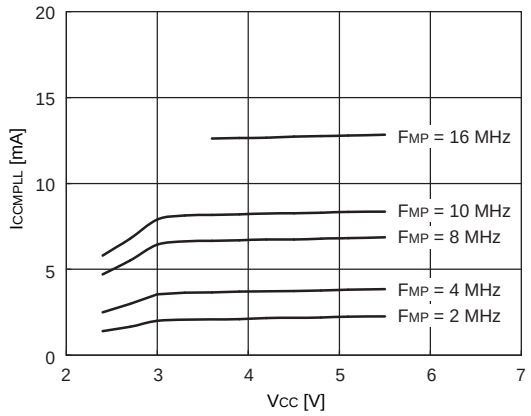
I_{CCS} – V_{CC}
T_A = + 25 °C, F_{MP} = 2, 4, 8, 10, 16 MHz (divided by 2)
Main sleep mode, at external clock operating



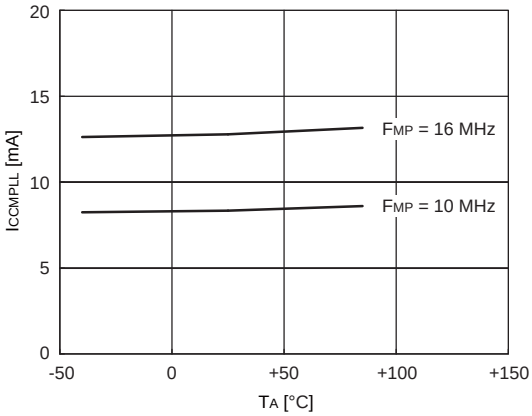
I_{CCS} – T_A
V_{CC} = 5.5 V, F_{MP} = 10, 16 MHz (divided by 2)
Main sleep mode, at external clock operating



I_{CCMPLL} – V_{CC}
T_A = + 25 °C, F_{MP} = 2, 4, 8, 10, 16 MHz
(Main PLL multiplied by 2.5)
Main PLL mode, at external clock operating

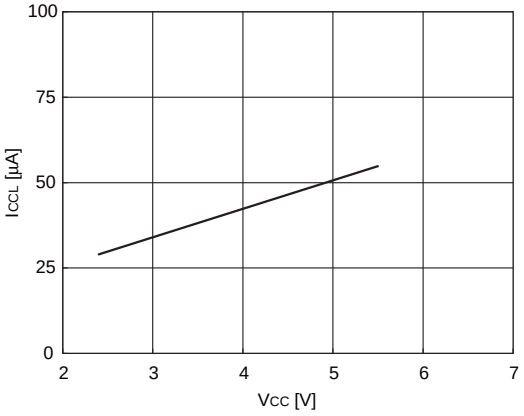


I_{CCMPLL} – T_A
V_{CC} = 5.5 V, F_{MP} = 10, 16 MHz (Main PLL multiplied by 2.5)
Main PLL mode, at external clock operating

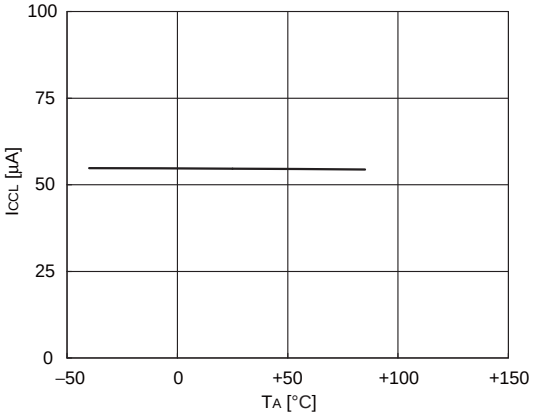


(Continued)

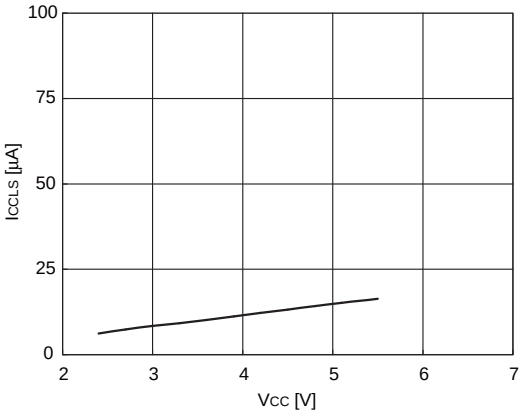
I_{CCL} – V_{CC}
T_A = + 25 °C, F_{MPL} = 16 kHz (divided by 2)
Sub clock mode, at external clock operating



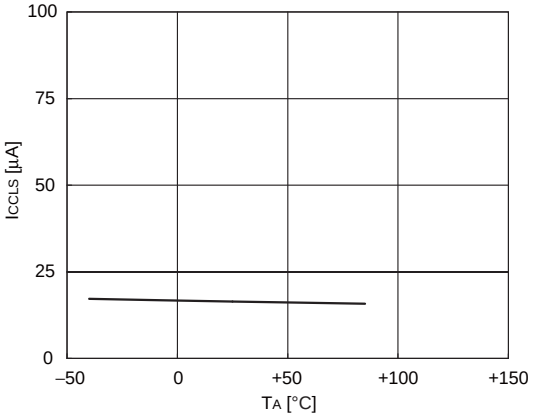
I_{CCL} – T_A
V_{CC} = 5.5 V, F_{MPL} = 16 kHz (divided by 2)
Sub clock mode, at external clock operating



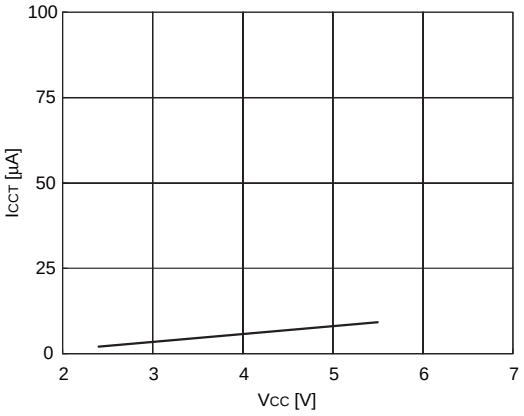
I_{CCLS} – V_{CC}
T_A = + 25 °C, F_{MPL} = 16 kHz (divided by 2)
Sub sleep mode, at external clock operating



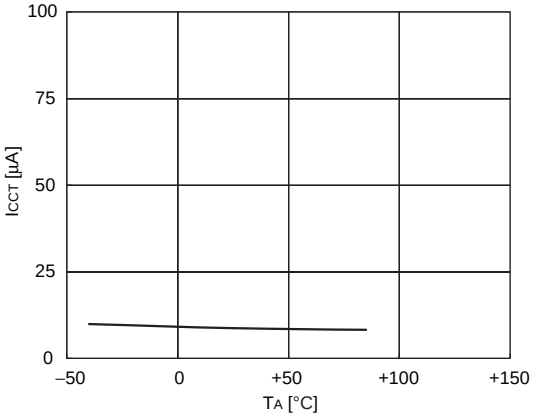
I_{CCLS} – T_A
V_{CC} = 5.5 V, F_{MPL} = 16 kHz (divided by 2)
Sub sleep mode, at external clock operating



I_{CCT} – V_{CC}
T_A = + 25 °C, F_{MPL} = 16 kHz (divided by 2)
Clock mode, at external clock operating



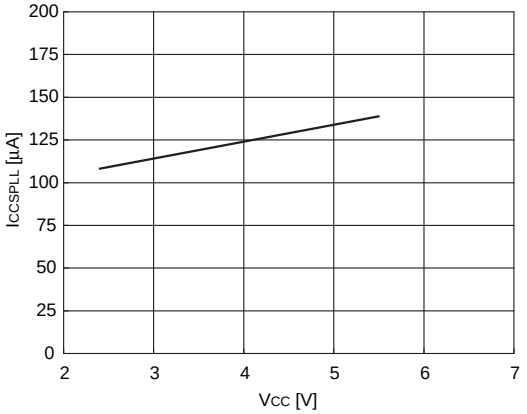
I_{CCT} – T_A
V_{CC} = 5.5 V, F_{MPL} = 16 kHz (divided by 2)
Clock mode, at external clock operating



(Continued)

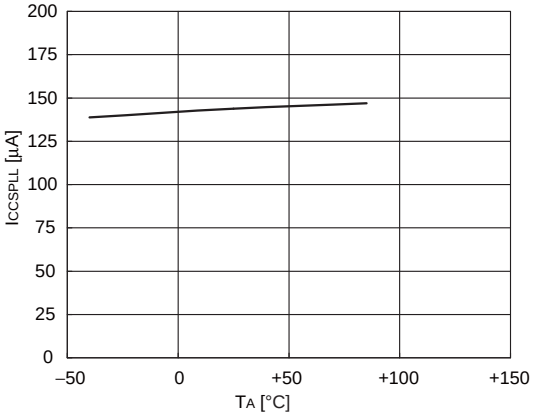
I_{CCSPLL} – V_{CC}

T_A = + 25 °C, F_{MPL} = 128 kHz (Main PLL multiplied by 4)
Sub PLL mode, at external clock operating



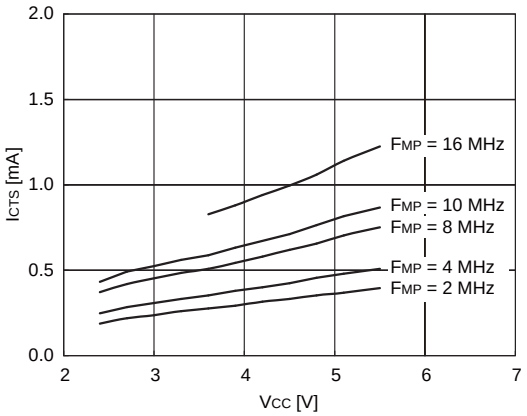
I_{CCSPLL} – T_A

V_{CC} = 5.5 V, F_{MPL} = 128 kHz (Main PLL multiplied by 4)
Sub PLL mode, at external clock operating



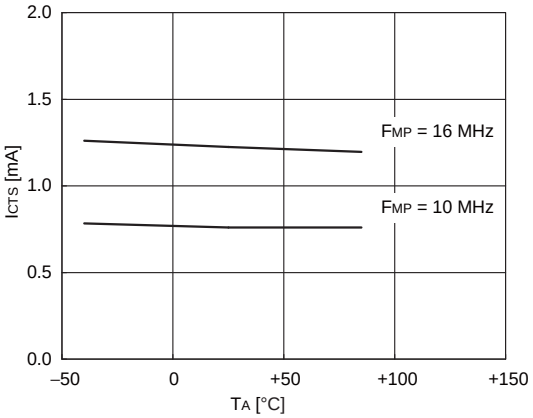
I_{CTS} – V_{CC}

T_A = + 25 °C, F_{MP} = 2, 4, 8, 10, 16 MHz (divided by 2)
Time-base timer mode, at external clock operating



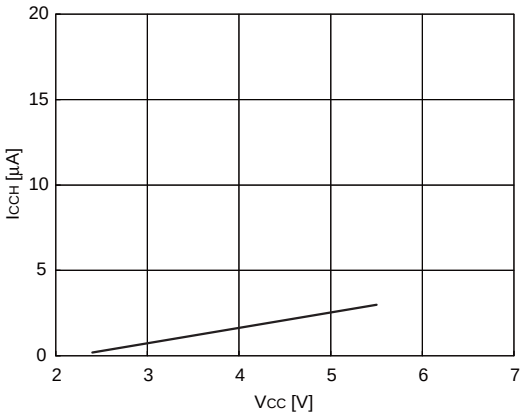
I_{CTS} – T_A

V_{CC} = 5.5 V, F_{MP} = 10, 16 MHz (divided by 2)
Time-base timer mode, at external clock operating



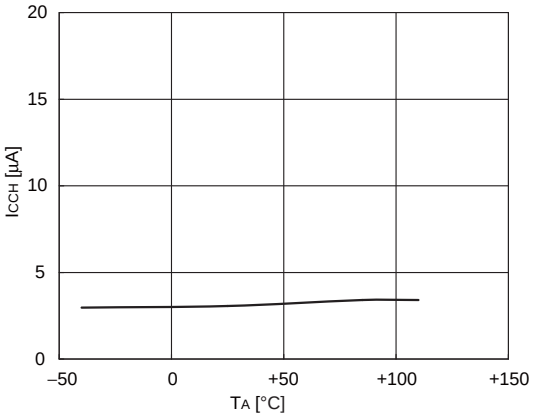
I_{CCH} – V_{CC}

T_A = + 25 °C, F_{MPL} = (stop)
Sub stop mode, at external clock stopping



I_{CCH} – T_A

V_{CC} = 5.5 V, F_{MPL} = (stop)
Sub stop mode, at external clock stopping

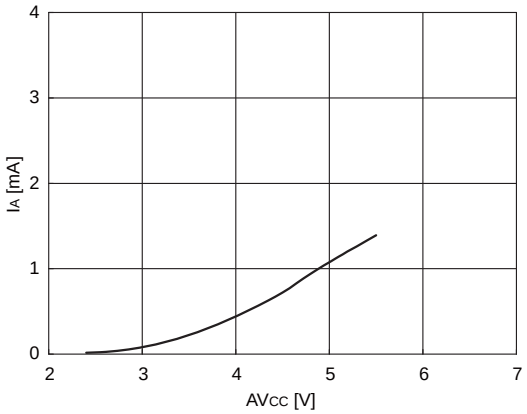


(Continued)

(Continued)

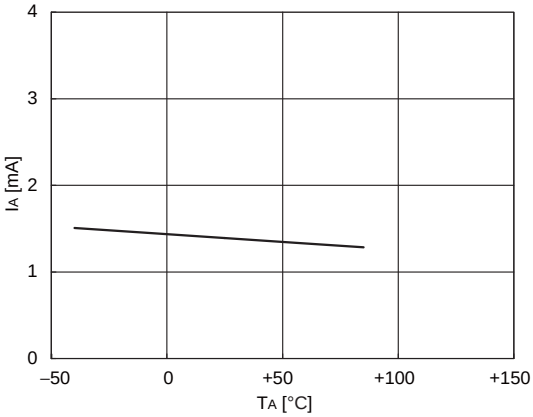
I_A – AV_{CC}

T_A = + 25 °C, F_{MP} = 16 MHz (divided by 2)
Main clock mode, at external clock operating



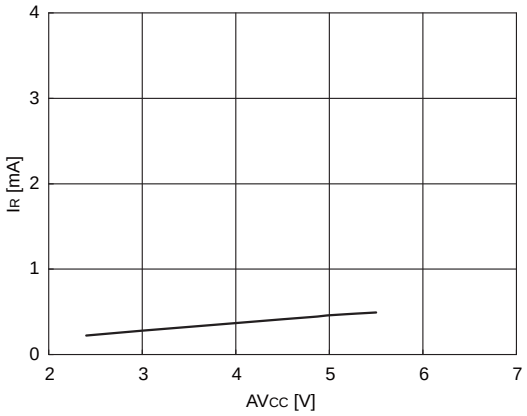
I_A – T_A

V_{CC} = 5.5 V, F_{MP} = 16 MHz (divided by 2)
Main clock mode, at external clock operating



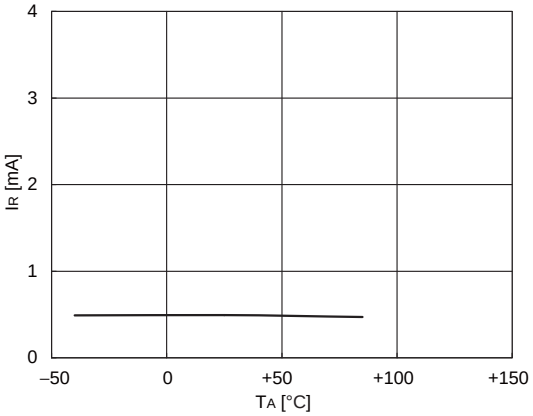
I_R – AV_{CC}

T_A = + 25 °C, F_{MP} = 16 MHz (divided by 2)
Main clock mode, at external clock operating



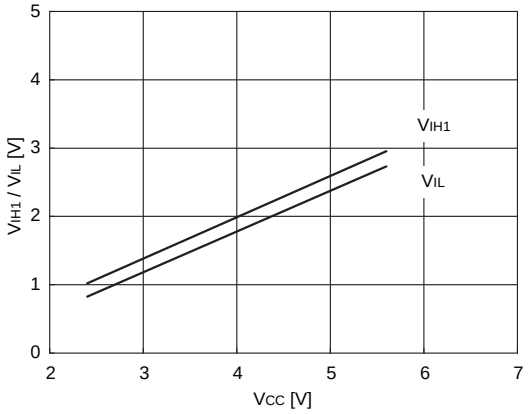
I_R – T_A

V_{CC} = 5.5 V, F_{MP} = 16 MHz (divided by 2)
Main clock mode, at external clock operating

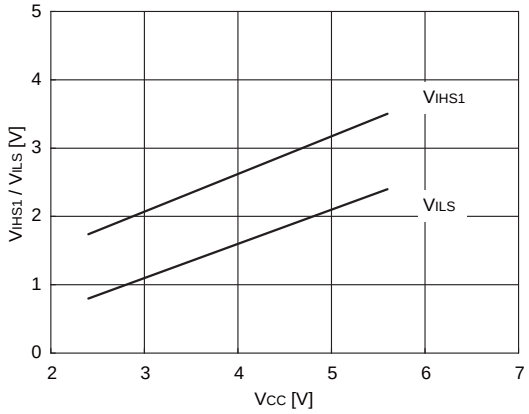


• **Input voltage (MB95F168MA/F168NA/F168JA)**

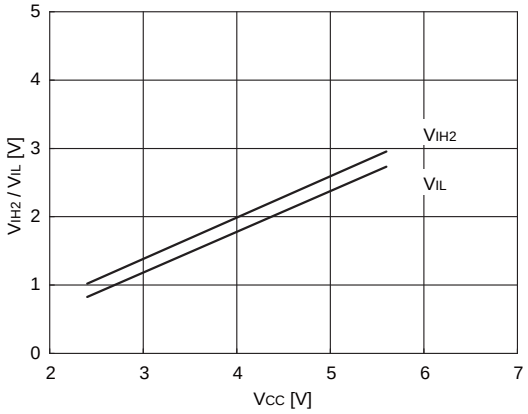
V_{IH1} – V_{CC} and V_{IL} – V_{CC}
T_A = + 25 °C



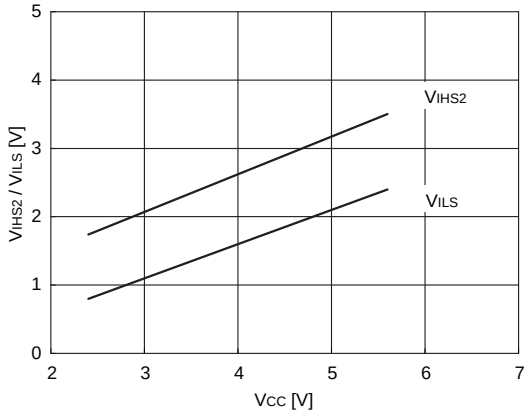
V_{IHS1} – V_{CC} and V_{ILS} – V_{CC}
T_A = + 25 °C



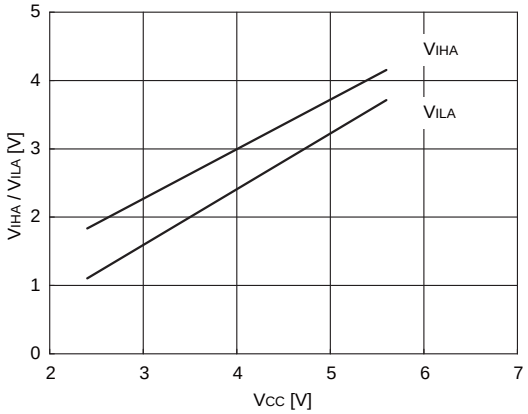
V_{IH2} – V_{CC} and V_{IL} – V_{CC}
T_A = + 25 °C



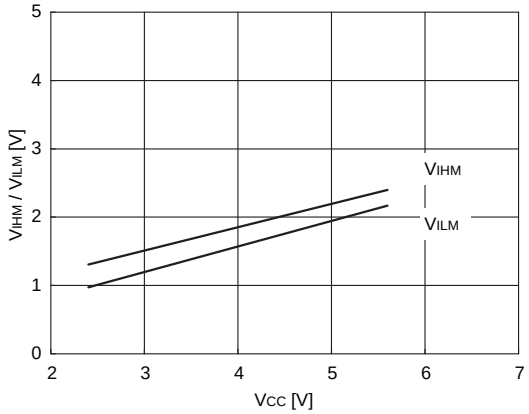
V_{IHS2} – V_{CC} and V_{ILS} – V_{CC}
T_A = + 25 °C



V_{IHA} – V_{CC} and V_{ILA} – V_{CC}
T_A = + 25 °C

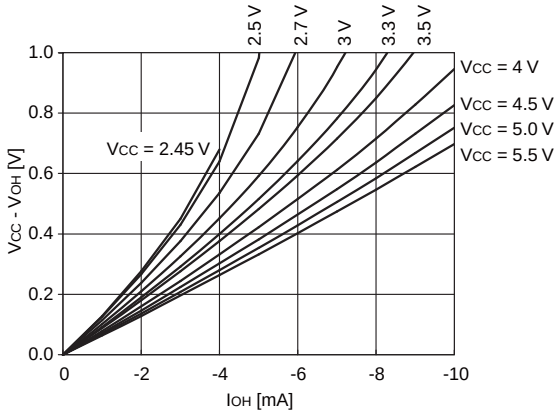


V_{IHM} – V_{CC} and V_{ILM} – V_{CC}
T_A = + 25 °C

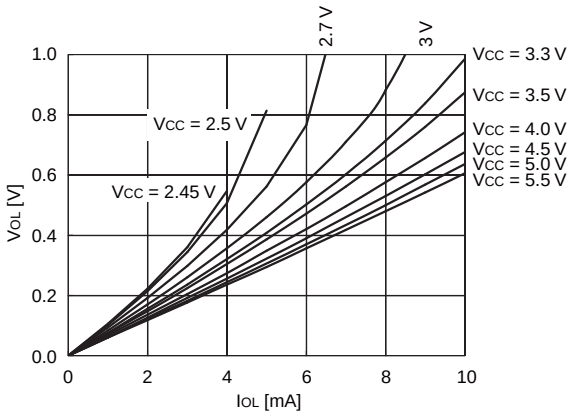


• **Output voltage (MB95F168MA/F168NA/F168JA)**

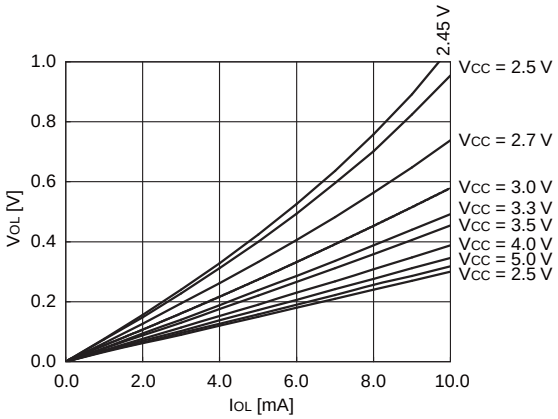
$(V_{CC} - V_{OH}) - I_{OH}$
$T_A = +25\ °C$



$V_{OL} - I_{OL}$
$T_A = +25\ °C$

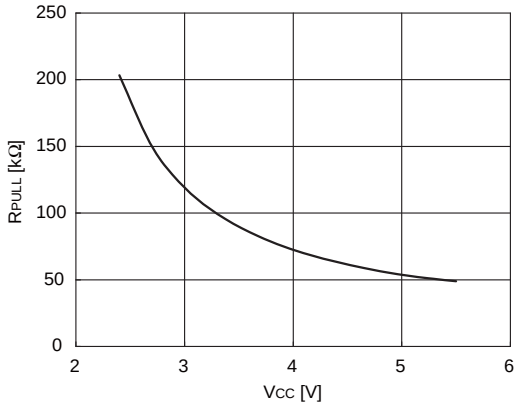


$V_{OL} - I_{OL}$
$T_A = +25\ °C$



• **Pull-up (MB95F168MA/F168NA/F168JA)**

$R_{PULL} - V_{CC}$
$T_A = +25\ °C$



■ MASK OPTION

No.	Part number	MB95168MA	MB95F168MA/ MB95F168NA/ MB95F168JA	MB95FV100D-103
	Specifying procedure	Specified when ordering ROM	Setting disabled	Setting disabled
1	Clock mode select* • Single-system clock mode • Dual-system clock mode	Dual-system clock mode	Dual-system clock mode	Changing by the switch on MCU board
2	Low voltage detection reset* • With low voltage detection reset • Without low voltage detection reset	Specified when ordering ROM	Specified by part number	Changing by the switch on MCU board
3	Clock supervisor* • With clock supervisor • Without clock supervisor	Specified when ordering ROM	Specified by part number	Changing by the switch on MCU board
4	Reset output* • With reset output • Without reset output	Specified when ordering ROM	Specified by part number	MCU board switch sets as follows; • With clock supervisor: Without reset output • Without clock supervisor: With reset output
5	Oscillation stabilization wait time	Fixed to oscillation stabilization wait time of $(2^{14} - 2) / F_{CH}$	Fixed to oscillation stabilization wait time of $(2^{14} - 2) / F_{CH}$	Fixed to oscillation stabilization wait time of $(2^{14} - 2) / F_{CH}$

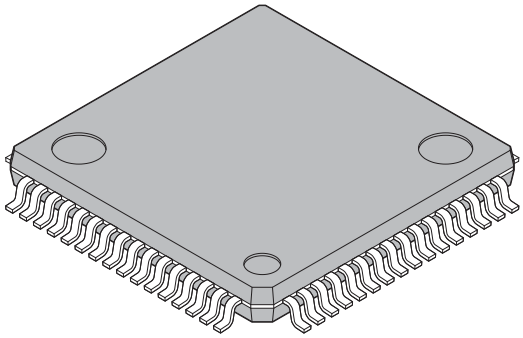
* : Refer to table below about clock mode select, low voltage detection reset, clock supervisor select and reset output.

Part number	Clock mode select	Low voltage detection reset	Clock supervisor	Reset output
MB95168MA	Dual-system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No
MB95F168MA	Dual-system	No	No	Yes
MB95F168NA		Yes	No	Yes
MB95F168JA		Yes	Yes	No
MB95FV100D-103	Single-system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No
	Dual-system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No

■ ORDERING INFORMATION

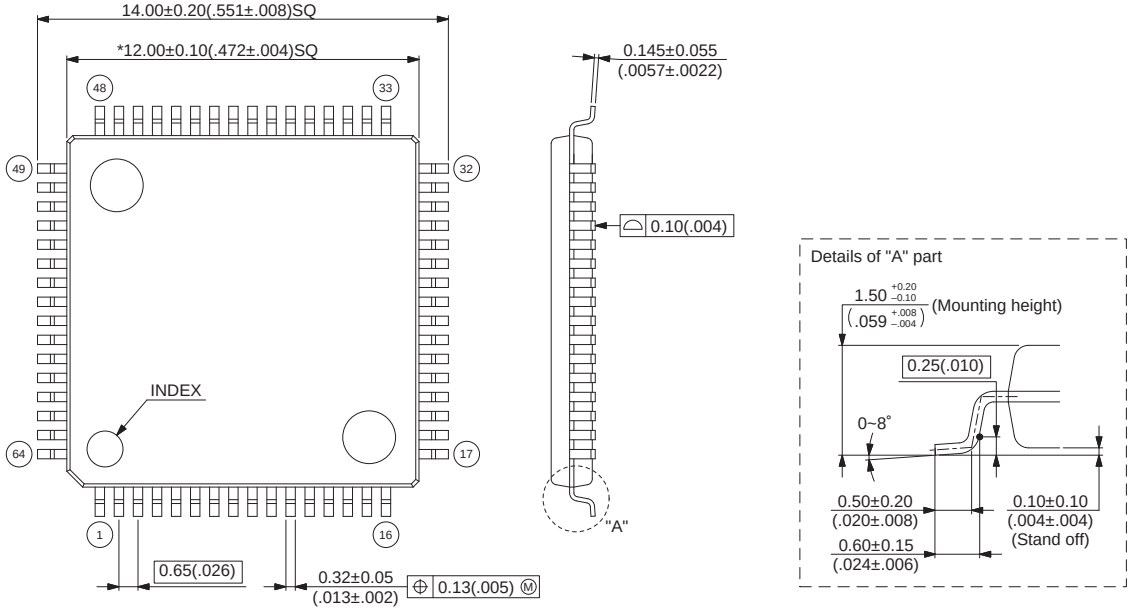
Part number	Package
MB95F168MAPMC MB95F168NAPMC MB95F168JAPMC MB95168MAPMC	64-pin plastic LQFP (FPT-64P-M23)
MB95F168MAPMC1 MB95F168NAPMC1 MB95F168JAPMC1 MB95168MAPMC1	64-pin plastic LQFP (FPT-64P-M24)
MB2146-303A-E (MB95FV100D-103PBT)	MCU board (224-pin plastic PFBGA (BGA-224P-M08))

■ PACKAGE DIMENSIONS

64-pin plastic LQFP		
 (FPT-64P-M23)	Lead pitch	0.65 mm
	Package width × package length	12.0 × 12.0 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.70 mm MAX
	Code (Reference)	P-LFQFP64-12×12-0.65

64-pin plastic LQFP
(FPT-64P-M23)

Note 1) * : These dimensions do not include resin protrusion.
Note 2) Pins width and pins thickness include plating thickness.
Note 3) Pins width do not include tie bar cutting remainder.



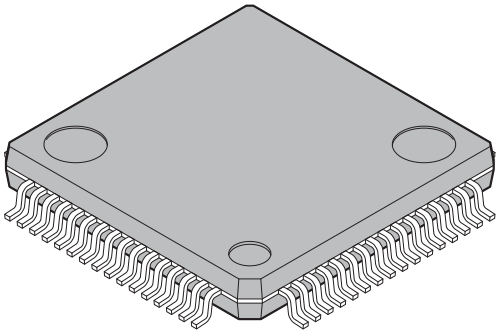
©2003-2008 FUJITSU MICROELECTRONICS LIMITED F64034S-c-1-2

Dimensions in mm (inches).
Note: The values in parentheses are reference values

Please confirm the latest Package dimension by following URL.
http://edevice.fujitsu.com/package/en-search/

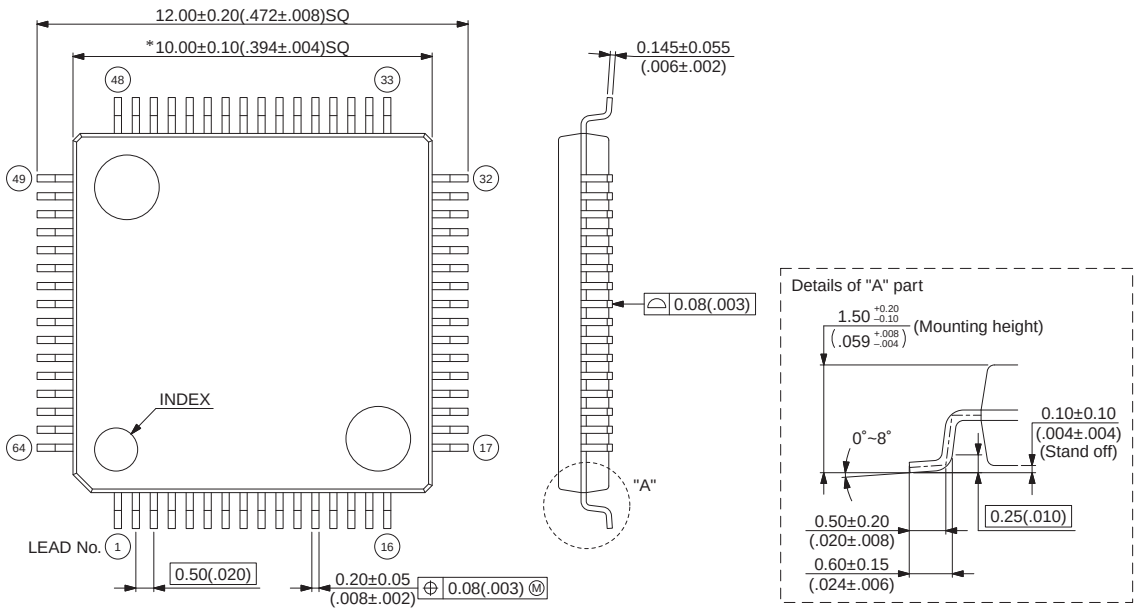
(Continued)

(Continued)

64-pin plastic LQFP		
 (FPT-64P-M24)	Lead pitch	0.50 mm
	Package width × package length	10.0 × 10.0 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.70 mm MAX
	Weight	0.32 g
	Code (Reference)	P-LFQFP64-10×10-0.50

64-pin plastic LQFP
(FPT-64P-M24)

Note 1) * : These dimensions do not include resin protrusion.
Note 2) Pins width and pins thickness include plating thickness.
Note 3) Pins width do not include tie bar cutting remainder.



©2005-2008 FUJITSU MICROELECTRONICS LIMITED F64036S-c-1-2

Dimensions in mm (inches).
Note: The values in parentheses are reference values

Please confirm the latest Package dimension by following URL.
http://edevice.fujitsu.com/package/en-search/

■ MAIN CHANGES IN THIS EDITION

Page	Section	Change Results
4	■ PRODUCT LINEUP	Changed the Note. (MB2146-303A → MB2146-303A-E).
14	■ HANDLING DEVICES	Added the item of " • Serial communication".
31	■ ELECTRICAL CHARACTERISTICS 2. Recommended Operating Conditions	Changed *2 under the table.
69	■ ORDERING INFORMATION	Changed the part number. (MB2146-303A → MB2146-303A-E).

The vertical lines marked in the left side of the page show the changes.

MEMO

MEMO

MEMO

FUJITSU MICROELECTRONICS LIMITED

Shinjuku Dai-Ichi Seimei Bldg., 7-1, Nishishinjuku 2-chome,
Shinjuku-ku, Tokyo 163-0722, Japan
Tel: +81-3-5322-3347 Fax: +81-3-5322-3387
http://jp.fujitsu.com/fml/en/

For further information please contact:

North and South America
FUJITSU MICROELECTRONICS AMERICA, INC.
1250 E. Arques Avenue, M/S 333
Sunnyvale, CA 94085-5401, U.S.A.
Tel: +1-408-737-5600 Fax: +1-408-737-5999
http://www.fma.fujitsu.com/

Europe
FUJITSU MICROELECTRONICS EUROPE GmbH
Pittlerstrasse 47, 63225 Langen, Germany
Tel: +49-6103-690-0 Fax: +49-6103-690-122
http://emea.fujitsu.com/microelectronics/

Korea
FUJITSU MICROELECTRONICS KOREA LTD.
206 Kosmo Tower Building, 1002 Daechi-Dong,
Gangnam-Gu, Seoul 135-280, Republic of Korea
Tel: +82-2-3484-7100 Fax: +82-2-3484-7111
http://kr.fujitsu.com/fmk/

Asia Pacific
FUJITSU MICROELECTRONICS ASIA PTE. LTD.
151 Lorong Chuan,
#05-08 New Tech Park 556741 Singapore
Tel : +65-6281-0770 Fax : +65-6281-0220
http://www.fmal.fujitsu.com/

FUJITSU MICROELECTRONICS SHANGHAI CO., LTD.
Rm. 3102, Bund Center, No.222 Yan An Road (E),
Shanghai 200002, China
Tel : +86-21-6146-3688 Fax : +86-21-6335-1605
http://cn.fujitsu.com/fmc/

FUJITSU MICROELECTRONICS PACIFIC ASIA LTD.
10/F., World Commerce Centre, 11 Canton Road,
Tsimshatsui, Kowloon, Hong Kong
Tel : +852-2377-0226 Fax : +852-2376-3269
http://cn.fujitsu.com/fmc/en/

Specifications are subject to change without notice. For further information please contact each office.

All Rights Reserved.
The contents of this document are subject to change without notice.
Customers are advised to consult with sales representatives before ordering.
The information, such as descriptions of function and application circuit examples, in this document are presented solely for the purpose of reference to show examples of operations and uses of FUJITSU MICROELECTRONICS device; FUJITSU MICROELECTRONICS does not warrant proper operation of the device with respect to use based on such information. When you develop equipment incorporating the device based on such information, you must assume any responsibility arising out of such use of the information.
FUJITSU MICROELECTRONICS assumes no liability for any damages whatsoever arising out of the use of the information.
Any information in this document, including descriptions of function and schematic diagrams, shall not be construed as license of the use or exercise of any intellectual property right, such as patent right or copyright, or any other right of FUJITSU MICROELECTRONICS or any third party or does FUJITSU MICROELECTRONICS warrant non-infringement of any third-party's intellectual property right or other right by using such information. FUJITSU MICROELECTRONICS assumes no liability for any infringement of the intellectual property rights or other rights of third parties which would result from the use of information contained herein.
The products described in this document are designed, developed and manufactured as contemplated for general use, including without limitation, ordinary industrial use, general office use, personal use, and household use, but are not designed, developed and manufactured as contemplated (1) for use accompanying fatal risks or dangers that, unless extremely high safety is secured, could have a serious effect to the public, and could lead directly to death, personal injury, severe physical damage or other loss (i.e., nuclear reaction control in nuclear facility, aircraft flight control, air traffic control, mass transport control, medical life support system, missile launch control in weapon system), or (2) for use requiring extremely high reliability (i.e., submersible repeater and artificial satellite).
Please note that FUJITSU MICROELECTRONICS will not be liable against you and/or any third party for any claims or damages arising in connection with above-mentioned uses of the products.
Any semiconductor devices have an inherent chance of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.
Exportation/release of any products described in this document may require necessary procedures in accordance with the regulations of the Foreign Exchange and Foreign Trade Control Law of Japan and/or US export control laws.
The company names and brand names herein are the trademarks or registered trademarks of their respective owners.

Edited: Sales Promotion Department